TENTATIVE TOSHIBA MOS DIGITAL INTEGRATED CIRCUIT SILICON GATE CMOS

32 Mbit (4 M × 8 bit) CMOS NAND E^2PROM

DESCRIPTION

The TC58V32AFT/ADC device is a single volt 32 M (34,603,008) bit NAND Electrically Erasable and Programmable Read Only Memory (NAND EEPROM) organized as 528 bytes × 16 pages × 512 blocks. The device has a 528 byte static register which allows the program and read data to be transferred between the register and the memory cell array in 528 byte increments. The erase operation is implemented in a single block unit (8K bytes + 256 bytes : 528 bytes × 16 pages).

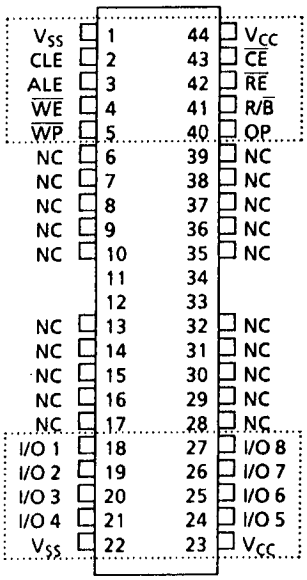
The TC58V32AFT/ADC is a serial type of memory device which utilizes the I/O pins for both address and data input / output as well as command inputs. The erase and program operations are automatically executed making the device most suitable for applications such as Solid State File Storage, Voice Recording, Image File Memory for still cameras and other systems which require large density, non-volatile memory data storage.

FEATURES

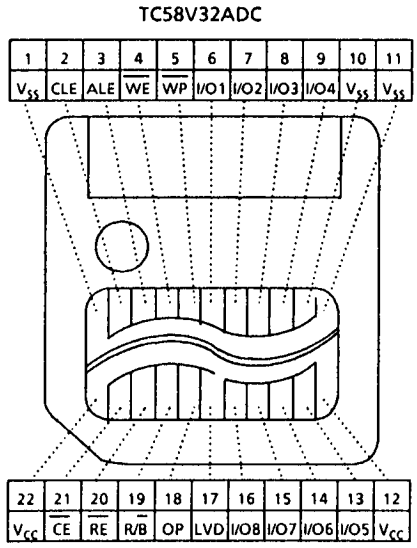
- Organization
  - Memory cell array 528 × 8 K × 8
  - Register 528 × 8
  - Page size 528 bytes
  - Block size (8 K + 256) bytes
- Mode
  - Read
  - Reset, Auto page program
  - Auto block erase, Status read
- Mode control
  - Serial input/output
  - Command control
- Power supply
  - TC58V32AFT : V_{CC} = 3.0 V to 5.5 V
  - TC58V32ADC : V_{CC} = 3.3 V ± 0.3 V
- Access time
  - Cell array - Register 10 μs max
  - Serial Read Cycle 50 ns min
- Operating current
  - Read (50ns cycle) 10 mA typ
  - Program (ave.) 10 mA typ
  - Erase (ave.) 10 mA typ
  - Standby 100 μA
- Package
  - TC58V32AFT : TSOP II 44/40 - P - 400 - 0.80B (Weight : 0.48 g Typ.)
  - TC58V32ADC : FDC - 22A (Weight : 1.8 g Typ.)

PIN ASSIGNMENT (TOP VIEW)

TC58V32AFT



TC58V32ADC



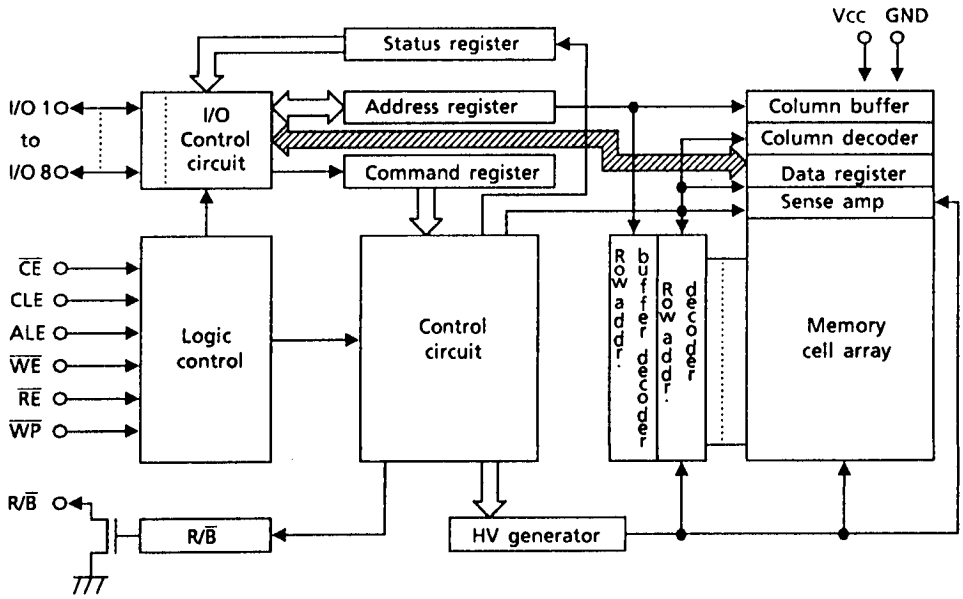
PIN ASSIGNMENT

$I/O_{1\ to\ 8}$	I/O port
$\overline{CE}$	Chip enable
$\overline{WE}$	Write enable
$\overline{RE}$	Read enable
CLE	Command latch enable
ALE	Address latch enable
$\overline{WP}$	Write protect
R/$\overline{B}$	Ready / Busy
OP	Option Pin
LVD	Low Voltage Detect
V_{CC}	Power supply
V_{SS}	Ground

OP : GND Input : 528 Byte / Page Operation
V_{CC} Input : 512 Byte / Page Operation

961001EBA1

BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

SYMBOL	RATING	VALUE		UNIT
		TC58V32AFT	TC58V32ADC	
V_{CC}	Power supply Voltage	− 0.6 to 6.0	− 0.6 to 4.6	V
V_{IN}	Input Voltage	− 0.6 to 6.0	− 0.6 to 4.6	V
$V_{I/O}$	Input / Output Voltage	− 0.6V to Vcc + 0.3V(≤ 6.0V)	− 0.6V to Vcc + 0.3V(≤ 4.6V)	V
P_D	Power Dissipation	0.5	0.5	W
T_{SOLDER}	Soldering Temperature (10 s)	260	−	°C
T_{STG}	Storage Temperature	− 55 to 150	− 20 to 65	°C
T_{OPR}	Operating Temperature	0 to 70	0 to 55	°C

CAPACITANCE *(Ta = 25°C, f = 1 MHz)

SYMBOL	PARAMETER	CONDITION	MIN	MAX	UNIT
C_{IN}	Input	V_{IN} = 0 V	−	10	pF
C_{OUT}	Output	V_{OUT} = 0 V	−	10	pF

* This parameter is periodically sampled and is not tested for every component.

VALID BLOCKS (1)

SYMBOL	PARAMETER	TC58V32AFT/ADC			UNIT
		MIN	TYP	MAX	
N_{VB}	Valid Block Number	502	508	512	Blocks

(1) The TC58V32AFT/ADC occasionally contains unusable blocks. Refer to Application Note (13) toward the end of this document.

DC RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	TC58V32AFT		TC58V32ADC		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Power Supply Voltage	3.0	5.5	3.0	3.6	V
V_{IH}	High Level Input Voltage	2.0*1/3.0*2	V_{CC} + 0.3	2.0	V_{CC} + 0.3	V
V_{IL}	Low Level Input Voltage	− 0.3 *3	0.8	− 0.3 *3	0.8	V

*1 : V_{CC} = 3.3V ± 0.3V
*2 : V_{CC} > 3.6V
*3 : − 2 V (pulse width ≤ 20 ns)

DC CHARACTERISTICS

(TC58V32AFT : Ta = 0° to 70°C, V_{CC} = 3.0 V to 5.5 V
(TC58V32ADC : Ta = 0° to 55 °C, V_{CC} = 3.3 V ± 0.3 V)

SYMBOL	PARAMETER	CONDITION	V_{CC} = 3.3 V ± 0.3 V			V_{CC} > 3.6 V			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
I_{IL}	Input Leak Current	V_{IN} = 0V~V_{CC}	−	−	± 10	−	−	± 10	μA
I_{LO}	Output Leak Current	V_{OUT} = 0.4V~V_{CC}	−	−	± 10	−	−	± 10	μA
I_{CCO1}	Operating Current (Serial Read)	$\overline{CE}$ = V_{IL}, Iout = 0mA, t_{cycle} = 50 ns	−	10	20	−	15	30	mA
I_{CCO3}	Operating Current (Command Input)	t_{cycle} = 50 ns	−	10	20	−	15	30	mA
I_{CCO4}	Operating Current (Data Input)	t_{cycle} = 50 ns	−	10	20	−	15	30	mA
I_{CCO5}	Operating Current (Address Input)	t_{cycle} = 50 ns	−	10	20	−	15	30	mA
I_{CCO7}	Programming Current	−	−	10	20	−	15	30	mA
I_{CCO8}	Erasing Current	−	−	10	20	−	15	30	mA
I_{CCS1}	Standby Current	$\overline{CE}$ = V_{IH}	−	−	1	−	−	1	mA
I_{CCS2}	Standby Current	$\overline{CE}$ = V_{CC} − 0.2 V	−	−	100	−	−	100	μA
V_{OH}	High Level Output Voltage	I_{OH} = -400 μA	2.4	−	−	2.4	−	−	V
V_{OL}	Low Level Output Voltage	I_{OL} = 2.1 mA	−	−	0.4	−	−	0.4	V
I_{OL} (R/$\overline{B}$)	Output Current of (R/$\overline{B}$) Pin	V_{OL} = 0.4 V	−	8	−	−	8	−	mA

AC CHARACTERISTICS AND OPERATING CONDITIONS

(TC58V32AFT : Ta = 0° to 70°C, V_{CC} = 3.0 V to 5.5 V)
(TC58V32ADC : Ta = 0° to 55 °C, V_{CC} = 3.3 V ± 0.3 V)

SYMBOL	PARAMETER	MIN	MAX	UNIT	NOTE
t_{CLS}	CLE Set-Up Time	0	–	ns	
t_{CLH}	CLE Hold Time	10	–	ns	
t_{CS}	$\overline{CE}$ Set-Up Time	0	–	ns	
t_{CH}	$\overline{CE}$ Hold Time	10	–	ns	
t_{WP}	Write Pulse Width	25	–	ns	
t_{ALS}	ALE Set-Up Time	0	–	ns	
t_{ALH}	ALE Hold Time	10	–	ns	
t_{DS}	Data Set-Up Time	20	–	ns	
t_{DH}	Data Hold Time	10	–	ns	
t_{WC}	Write Cycle Time	50	–	ns	
t_{WH}	$\overline{WE}$ High Hold Time	15	–	ns	
t_{WW}	$\overline{WP}$ High to $\overline{WE}$ Low	100	–	ns	
t_{RR}	Ready to $\overline{RE}$ Falling Edge	20	–	ns	
t_{RP}	Read Pulse Width	35	–	ns	
t_{RC}	Read Cycle Time	50	–	ns	
t_{REA}	$\overline{RE}$ Access Time (Serial Data Access)	–	35	ns	
t_{CEH}	$\overline{CE}$ High Time for the Last Address in Serial Read Cycle	100	–	ns	(3)
t_{REAID}	$\overline{RE}$ Access Time (ID Read)	–	35	ns	
t_{OH}	Data Output Hold Time	10	–	ns	
t_{RHZ}	$\overline{RE}$ High to Output High Impedance	–	30	ns	
t_{CHZ}	$\overline{CE}$ High to Output High Impedance	–	20	ns	
t_{REH}	$\overline{RE}$ High Hold Time	15	–	ns	
t_{IR}	Output High Impedance to $\overline{RE}$ Rising Edge	0	–	ns	
t_{RSTO}	$\overline{RE}$ Access Time (Status Read)	–	35	ns	
t_{CSTO}	$\overline{CE}$ Access Time (Status Read)	–	45	ns	
t_{RHW}	$\overline{RE}$ High to $\overline{WE}$ Low	0	–	ns	
t_{WHC}	$\overline{WE}$ High to $\overline{CE}$ Low	30	–	ns	
t_{WHR}	$\overline{WE}$ High to $\overline{RE}$ Low	30	–	ns	
t_{AR1}	ALE Low to $\overline{RE}$ Low (ID Read)	100	–	ns	
t_{CR}	$\overline{CE}$ Low to $\overline{RE}$ Low (ID Read)	100	–	ns	
t_R	Memory Cell Array to Starting Address	–	10	μs	
t_{WB}	$\overline{WE}$ High to Busy	–	200	ns	
t_{AR2}	ALE Low to $\overline{RE}$ Low (Read Cycle)	50	–	ns	
t_{RB}	$\overline{RE}$ Last Clock Rising Edge to Busy (in Sequential Read)	–	200	ns	
t_{CRY}	$\overline{CE}$ High to Ready (in Case of Interception by $\overline{CE}$ in Read Mode)	–	50 + tr ($R/\overline{B}$)	ns	(2)
t_{RST}	Device Resetting Time (Read/Program/Erase)	–	6/10/500	μs	

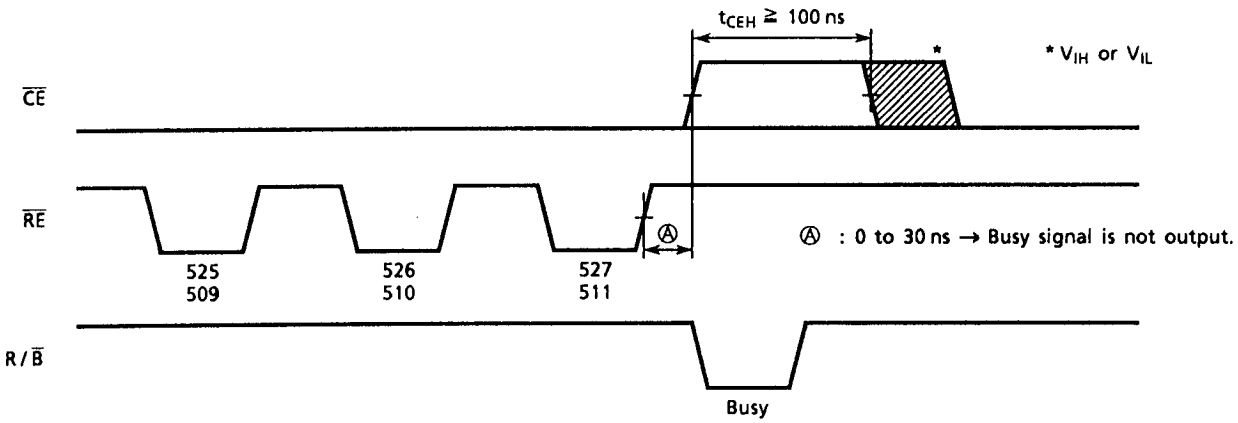
AC TEST CONDITIONS

Input level	:	2.4V/0.4V(V_{CC}=3.3V±0.3V) 3.4V/0.4V(V_{CC}>3.6V)
Input comparison level	:	1.5 V / 1.5 V
Output data comparison level	:	1.5 V / 1.5 V
Output load	:	1TTL & C_L (100 pF)

(1) Transition time (t_T) = 5 ns

(2) $\overline{CE}$ High to Ready time depends on the pull-up resistor tied to the R/$\overline{B}$ pin. (Refer to Application Note (10) toward the end of this document.)

(3) If the delay between $\overline{RE}$ and $\overline{CE}$ is less than 200 ns and t_{CEH} is greater than or equal to 100 ns, reading will stop.
If the $\overline{RE}$-to-$\overline{CE}$ delay is less than 30 ns, the device will not turn to the Busy state.



PROGRAMMING AND ERASING CHARACTERISTICS

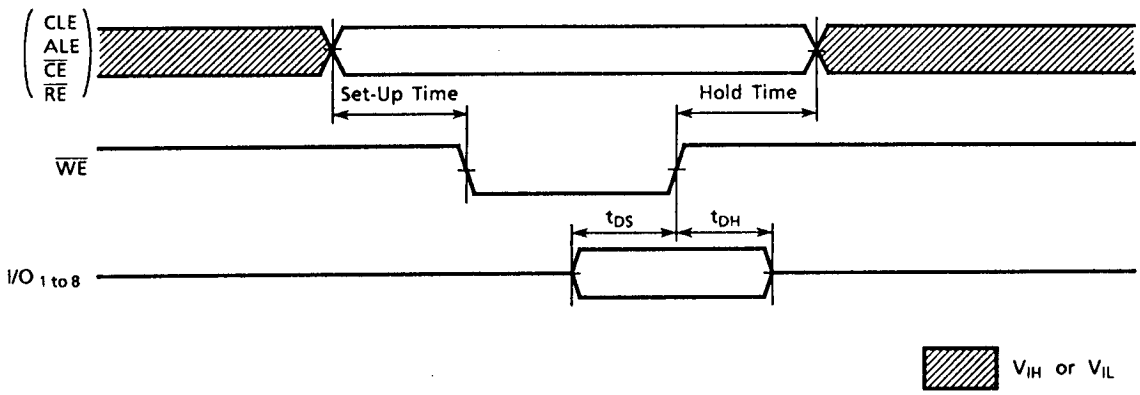
(TC58V32AFT : Ta = 0° to 70 °C, V_{CC} = 3.0 V to 5.5 V)
(TC58V32ADC : Ta = 0° to 55 °C, V_{CC} = 3.3 V ± 0.3 V)

SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT	NOTE
t_{PROG}	Average Programming Time		300	1000	μs	
N	Number of Programming Cycles on Same Page			10		(1)
t_{BERASE}	Block Erasing Time		2	30	ms	
P/E	Number of Program/Erase Cycles			1×10^6		(2)

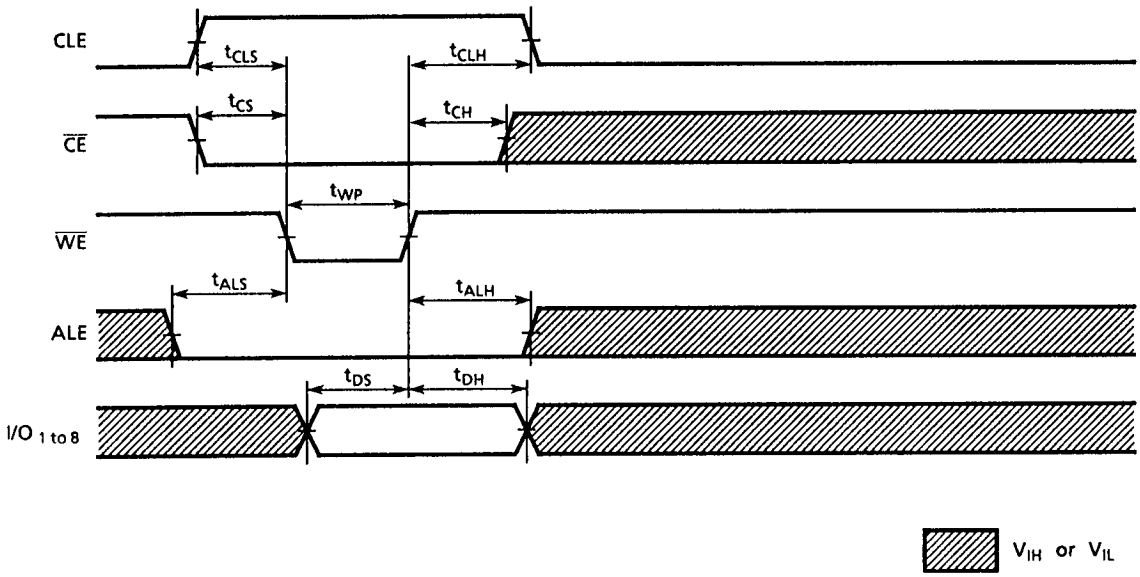
(1) Refer to Application Note (11) toward the end of this document.
(2) Refer to Application Note (14) toward the end of this document.

TIMING DIAGRAMS

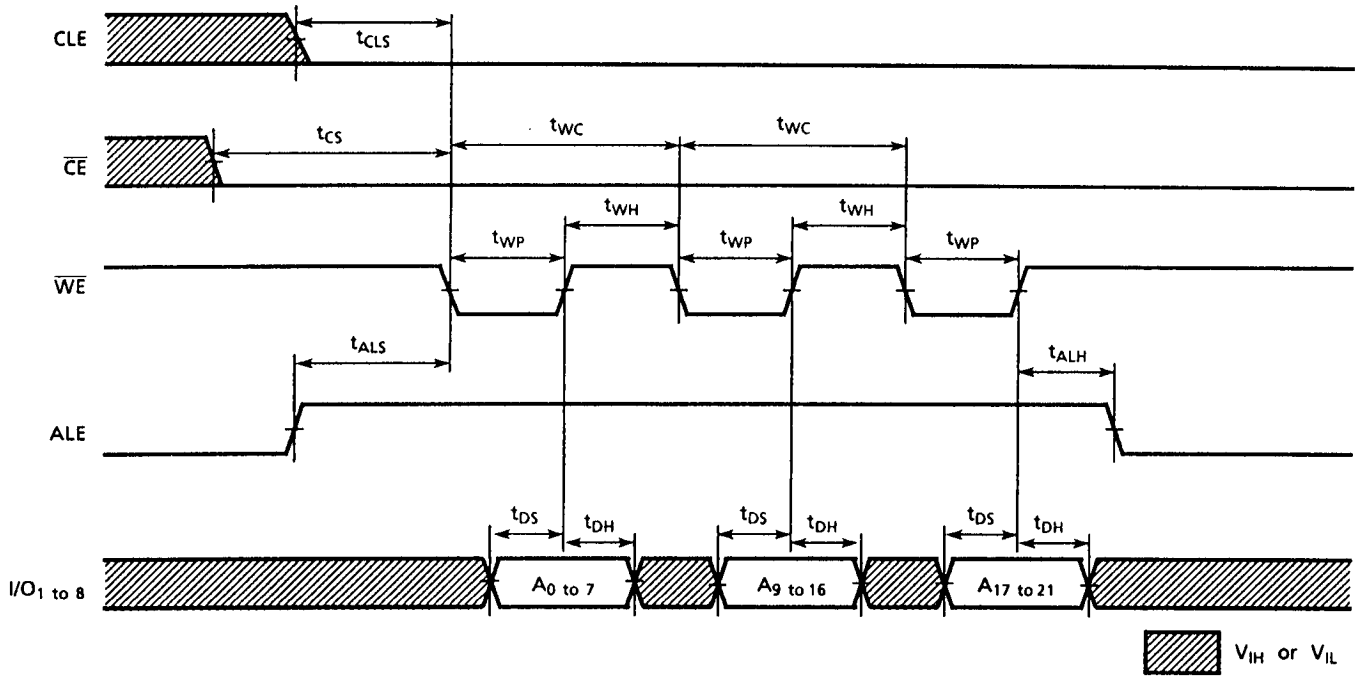
Latch Timing Diagram for Command/Address/Data



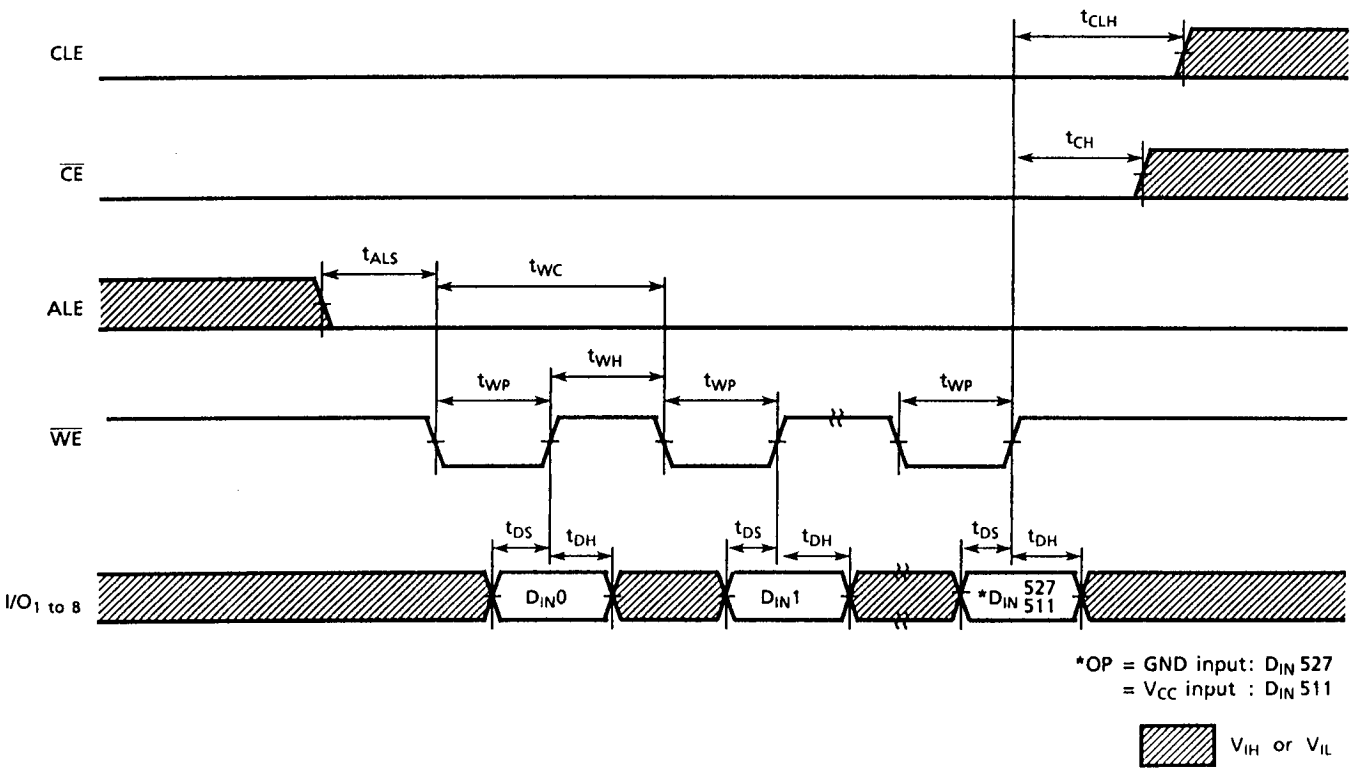
Command Input Cycle Timing Diagram



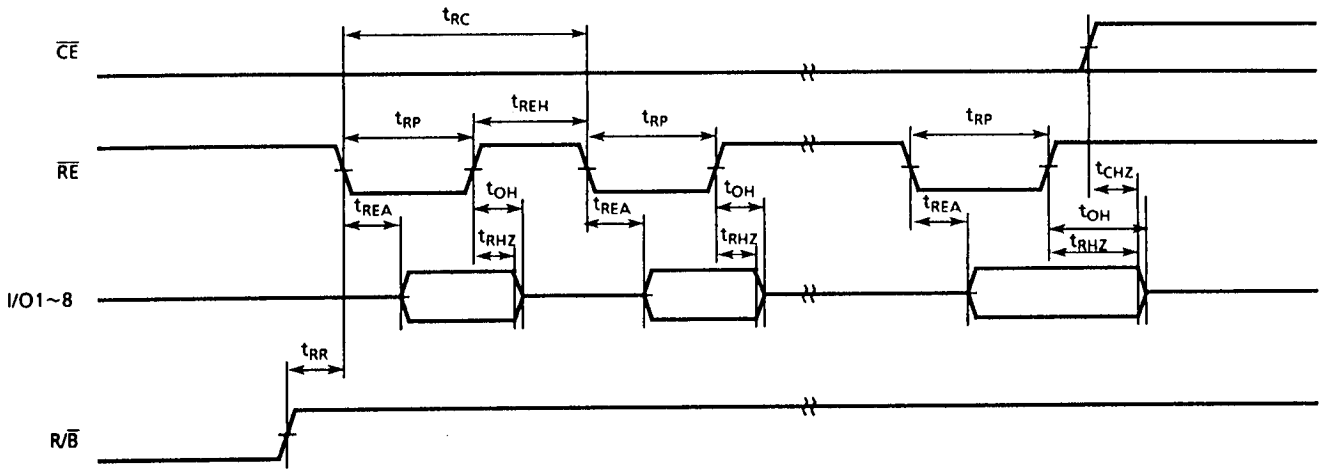
Address Input Cycle Timing Diagram



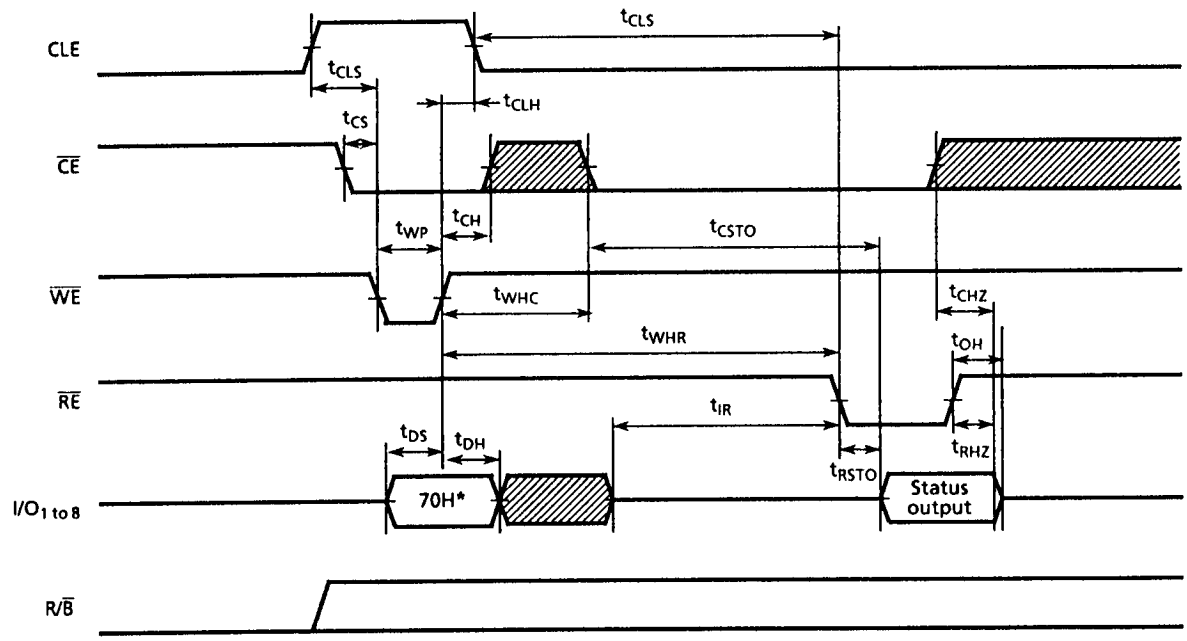
Data Input Cycle Timing Diagram



Serial Read Cycle Timing Diagram



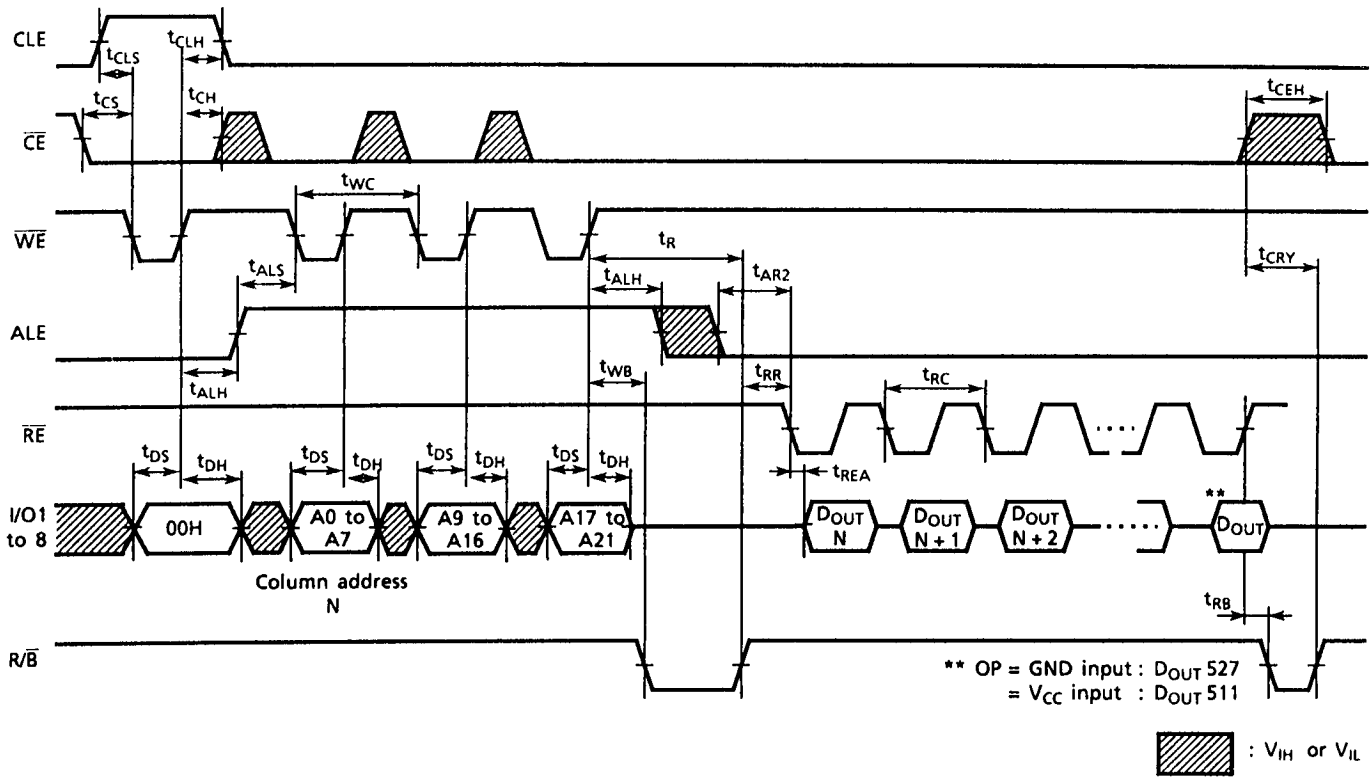
Status Read Cycle Timing Diagram



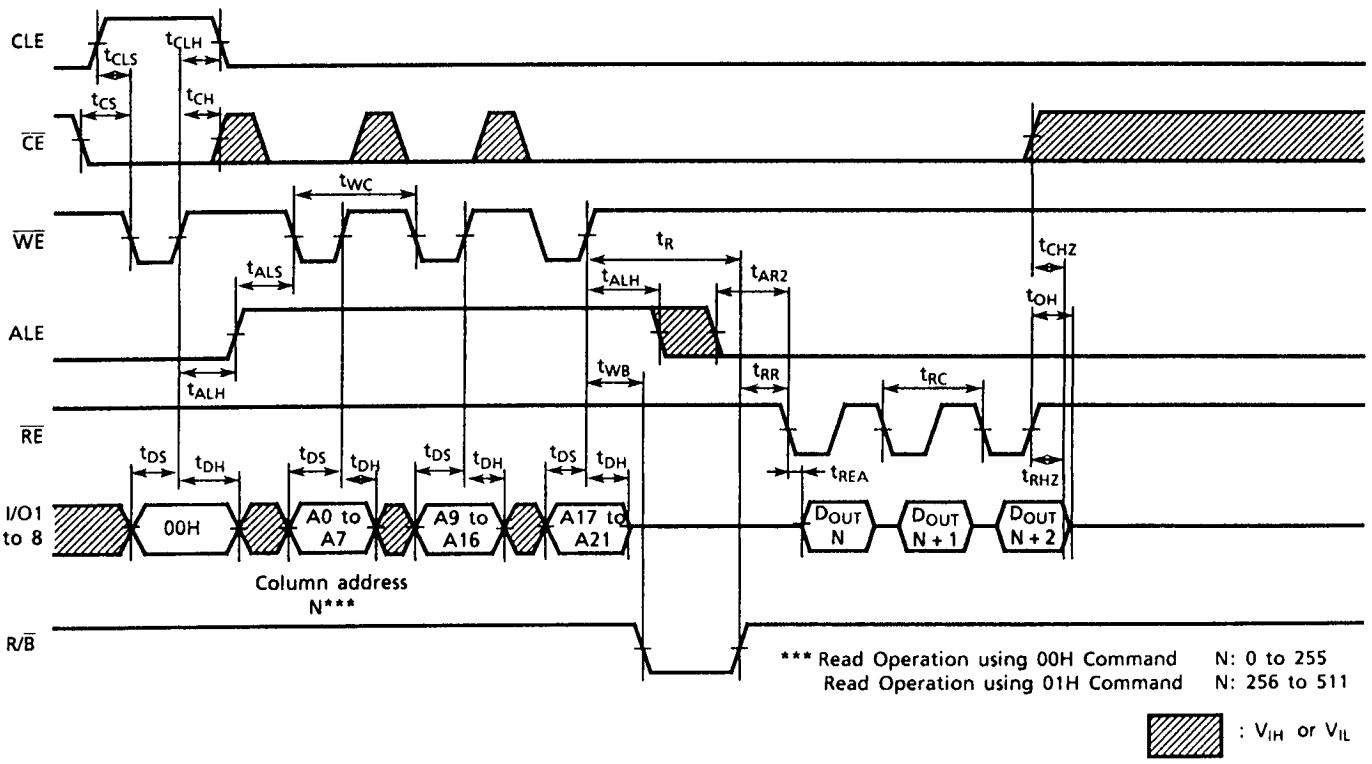
* 70H - 70 in HEX data

: V_{IH} or V_{IL}

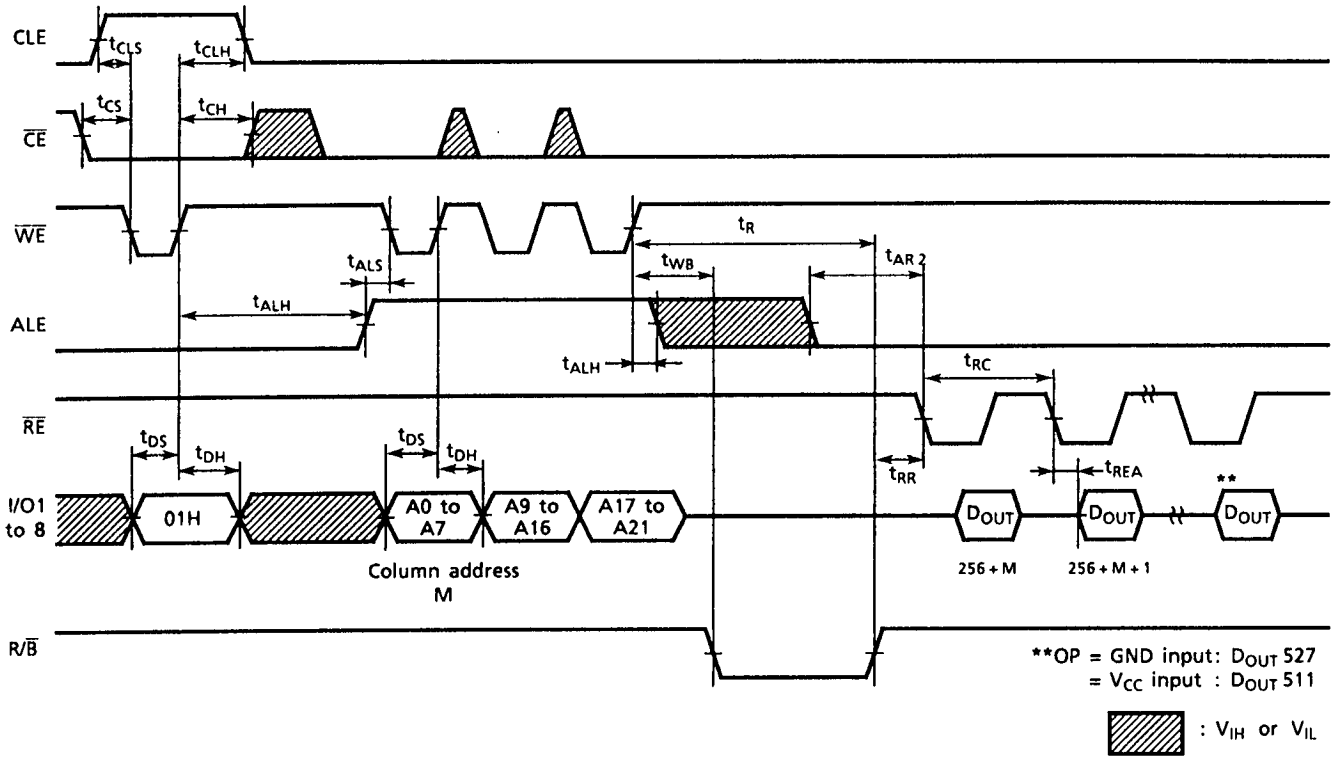
Read Cycle (1) Timing Diagram



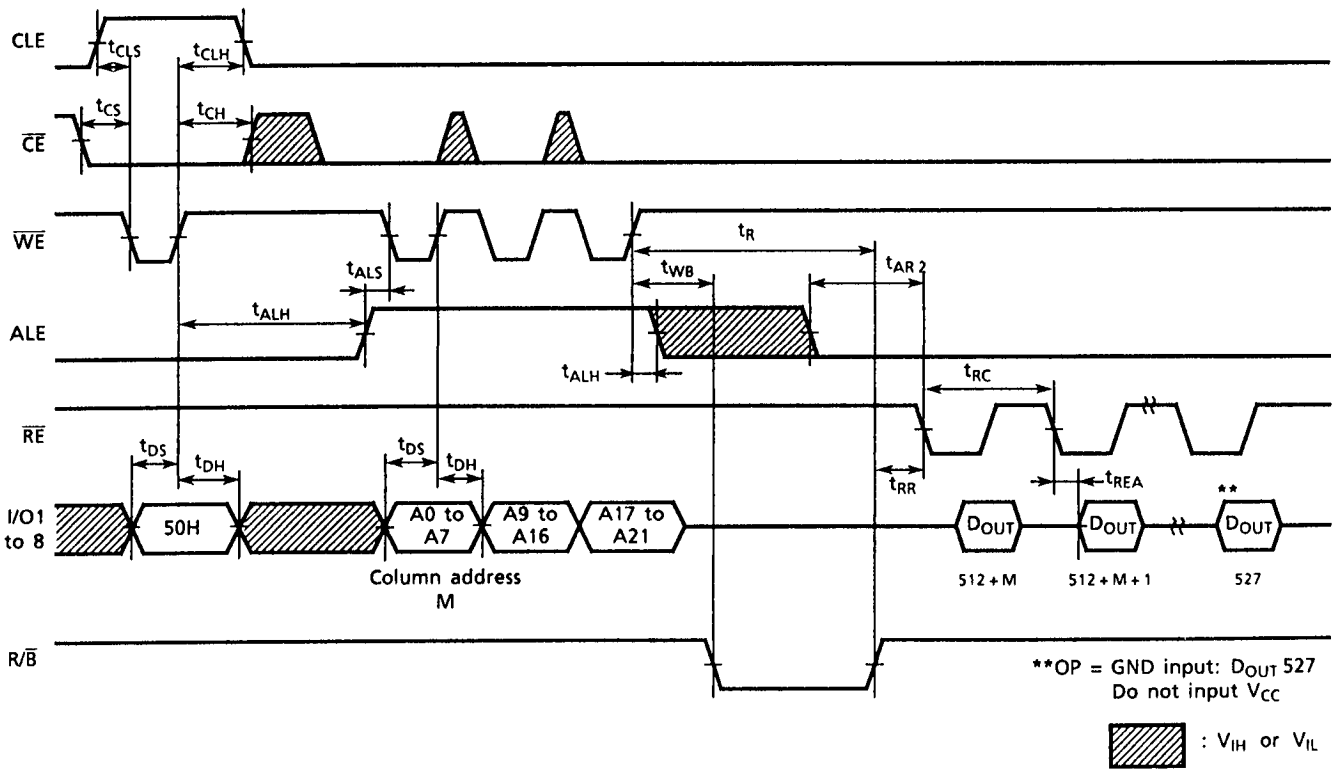
Read Cycle (1) Timing Diagram: Interrupted by $\overline{CE}$



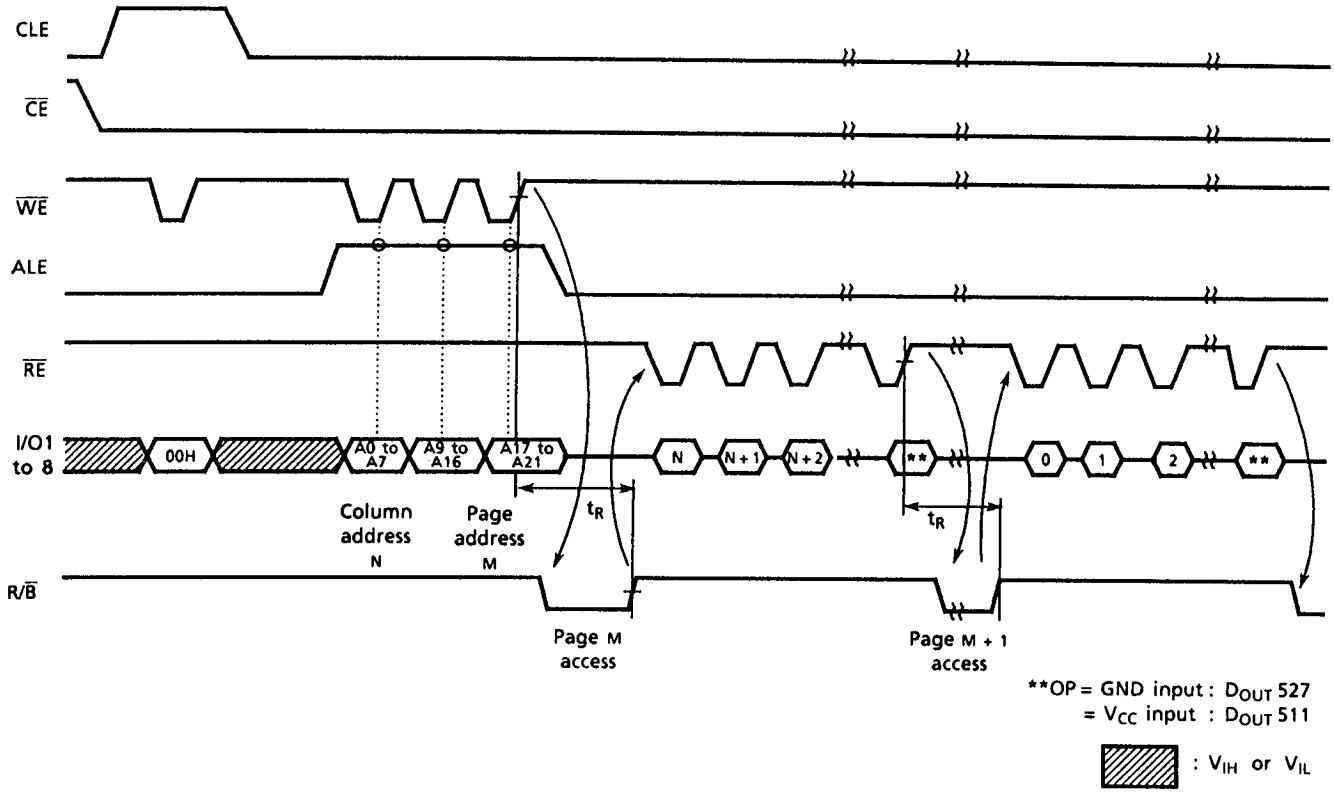
Read Cycle (2) Timing Diagram



Read Cycle (3) Timing Diagram



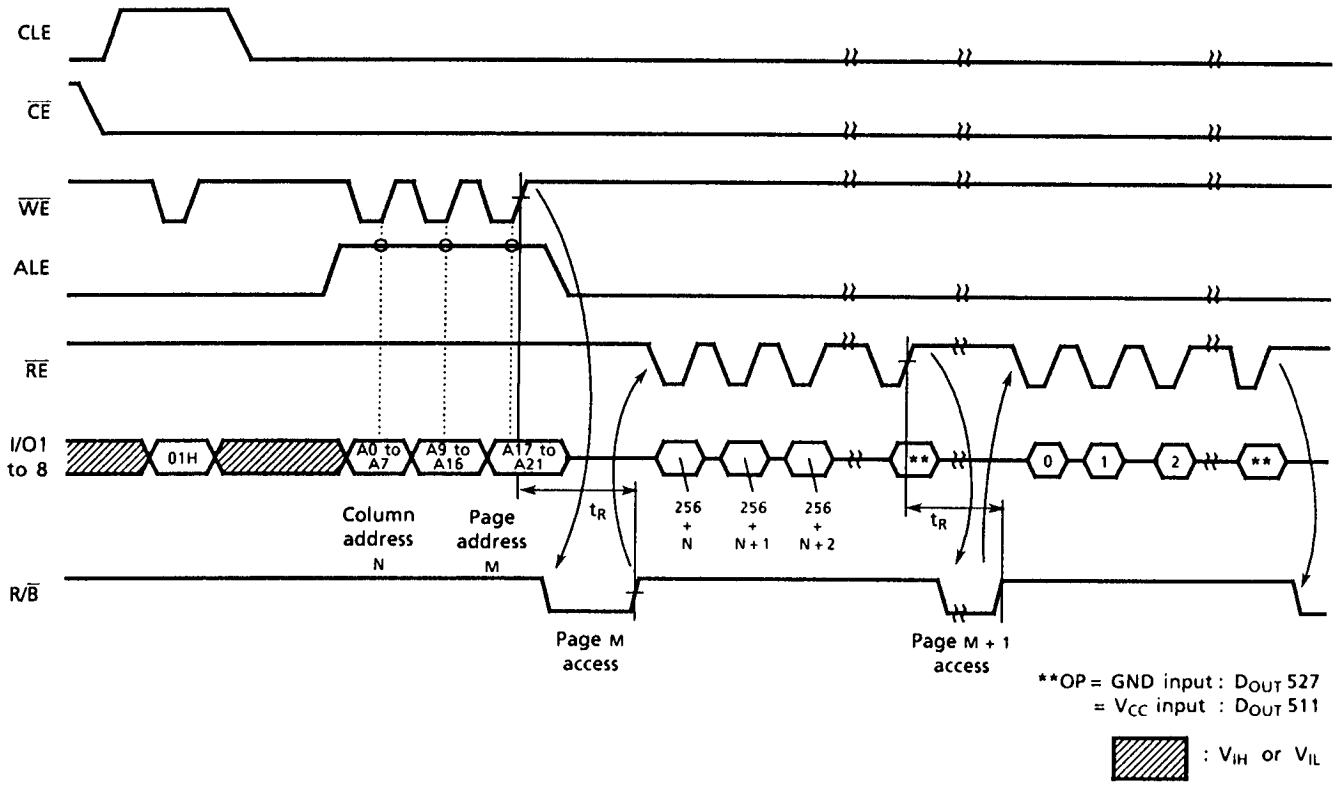
Sequential Read (1) Timing Diagram



**OP = GND input : D_{OUT} 527
= V_{CC} input : D_{OUT} 511

: V_{IH} or V_{IL}

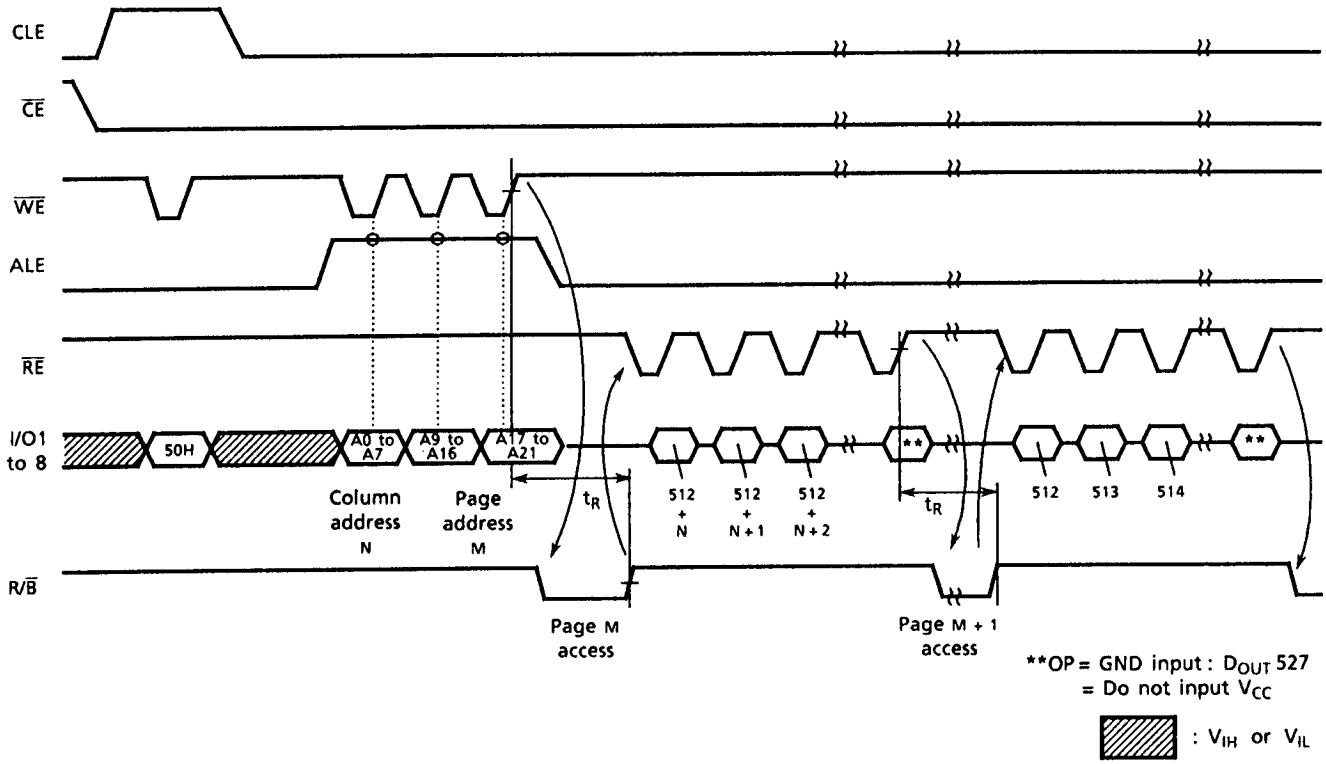
Sequential Read (2) Timing Diagram



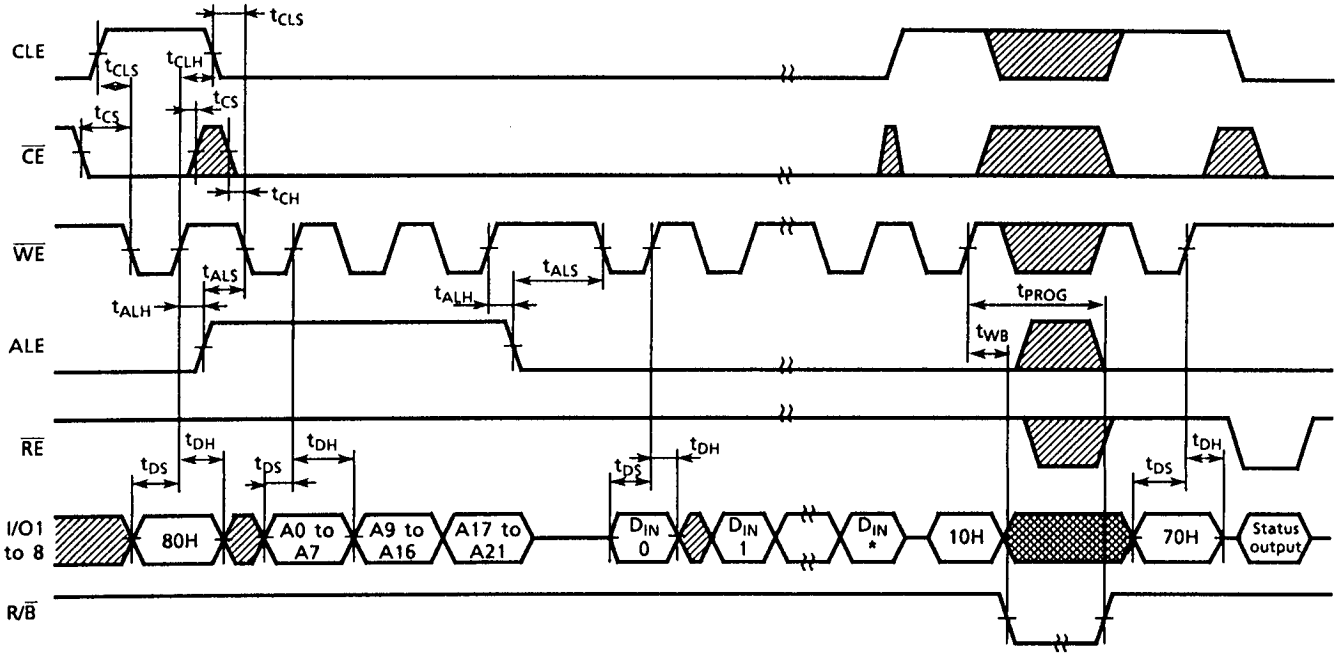
**OP = GND input : D_{OUT} 527
= V_{CC} input : D_{OUT} 511

: V_{IH} or V_{IL}

Sequential Read (3) Timing Diagram



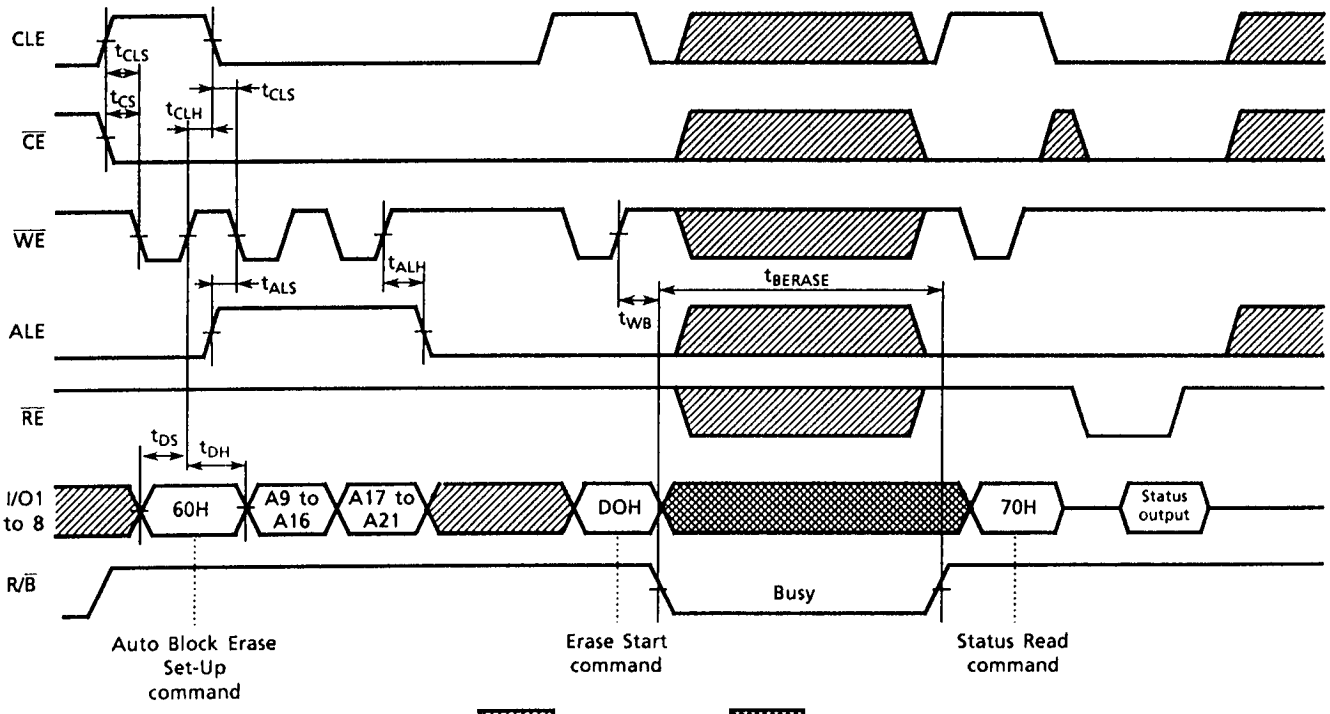
Auto Program Operation Timing Diagram



*OP = GND input: D_{IN} 527
= V_{CC} input : D_{IN} 511

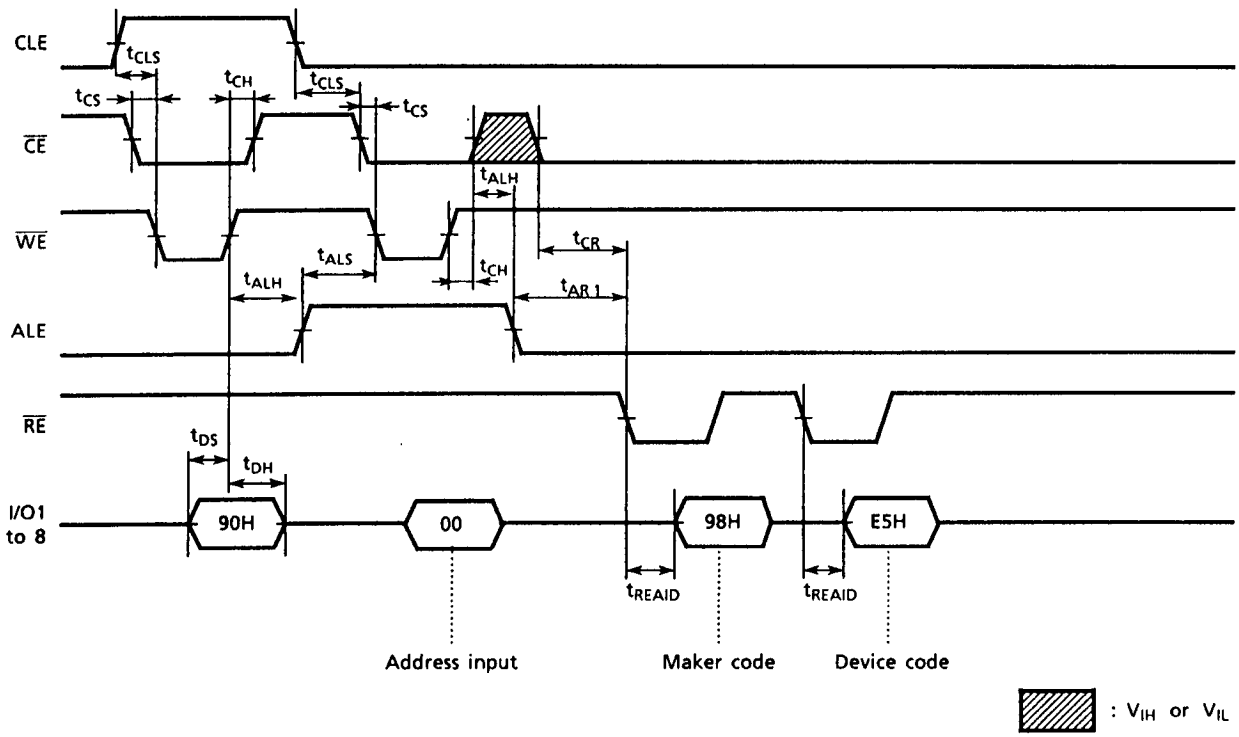
: V_{IH} or V_{IL} : If data is being output, do not allow any input.

Auto Block Erase Timing Diagram



: V_{IH} or V_{IL} : If data is being output, do not allow any input.

ID Read Operation Timing Diagram



PIN FUNCTIONS

The device is a serial access memory which utilizes time-sharing input of address information. The device pin-outs are configured as shown in Figure 1.

Command Latch Enable: CLE

The CLE input signal is used to control the acquisition of the operation mode command into the internal command register. The command is latched into the command register from the I/O port on the rising edge of the $\overline{WE}$ signal while CLE is high.

Address Latch Enable: ALE

The ALE signal is used to control the acquisition of either address information or input data into the internal address/data resistor. Address information is latched on the rising edge of $\overline{WE}$ if ALE is high. Input data is latched if ALE is low.

Chip Enable: $\overline{CE}$

The device goes into a low power standby mode during a Read operation when $\overline{CE}$ goes high. The $\overline{CE}$ signal is ignored when the device is in the Busy state ($R/\overline{B}$ = L), such as during a Program or Erase operation, and will not go into Standby mode even if a $\overline{CE}$ goes high input. The $\overline{CE}$ pin must stay low during the Read mode Busy state to ensure that memory signal array data is correctly transferred to the data register.

Write Enable: $\overline{WE}$

The $\overline{WE}$ signal is used to control the acquisition of data from the I/O port.

Read Enable: $\overline{RE}$

The $\overline{RE}$ signal controls serial data output. Data is available t_{REA} after the falling edge of $\overline{RE}$.
The internal column address counter is also incremented (Address + 1) on this falling edge.

I/O Port: I/O 1 to 8

The I/O 1 to 8 pins are used as the port for transferring address, command and input/output data to or from the device.

Write Protect: $\overline{WP}$

The $\overline{WP}$ signal is used to protect the device from accidental programming or erasing. The internal voltage regulator is reset when $\overline{WP}$ is low. This signal is usually used for protecting the data during the power on/off sequence when input signals are invalid.

Ready/Busy: $R/\overline{B}$

The $R/\overline{B}$ output signal is used to indicate the operating condition of the device. The $R/\overline{B}$ signal is in the Busy state ($R/\overline{B}$ = L) during the Program, Erase or Read operations and will return to Ready state ($R/\overline{B}$ = H) after completion of the operation. The output buffer for this signal is an open drain.

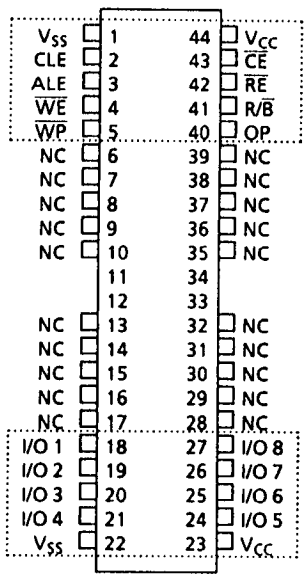
Option Pin: OP

The OP signal is used to change the page size. The device is in 528 byte/page mode when OP = GND, and 512 byte/page mode when OP = V_{CC}.

Low Voltage Detect: LVD

The LVD is used to detect the proper supply voltage. By connecting this pin to V_{SS} through a pull-down resistor, it is possible to distinguish 3.3V product (TC58V32DC) from 5V product (TC5832DC). When 3.3V is applied as V_{CC} to pins 12 and 22, a "H" level can be detected on the system side if the device is a 3.3V product, and "L" level for a 5V product.

TC58V32AFT



TC58V32ADC

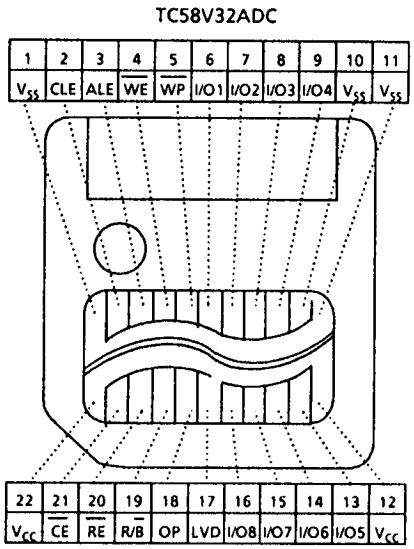


Figure 1. Pinout

Schematic Cell Layout and Address Assignment

The Program operation is implemented in a page units while the Erase operation is carried out in block units.

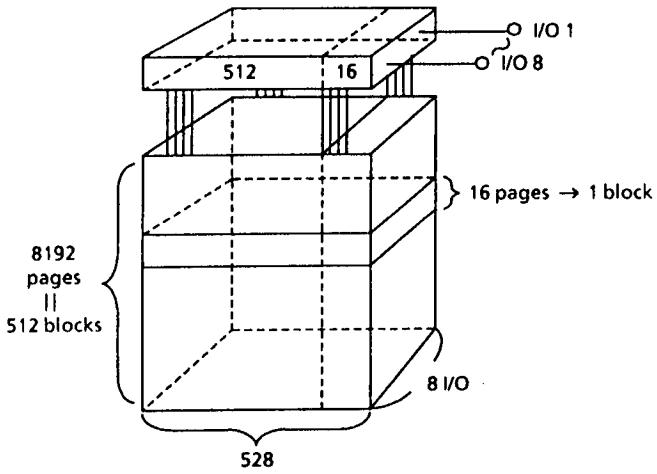


Figure 2. Schematic Cell Layout

A page consists of 528 bytes in which 512 bytes are for main memory and 16 bytes are for redundancy or other uses.

1 Page = 528 bytes
1 Block = 528 bytes × 16 pages = (8 K + 256) bytes
Total Device Density = 528 bytes × 16 pages × 512 blocks

The address is acquired through the I/O port over three consecutive clock cycles, as shown in Table 1.

Table 1. Addressing

	I/O 1	I/O 2	I/O 3	I/O 4	I/O 5	I/O 6	I/O 7	I/O 8
First cycle	A0	A1	A2	A3	A4	A5	A6	A7
Second cycle	A9	A10	A11	A12	A13	A14	A15	A16
Third cycle	A17	A18	A19	A20	A21	*L	*L	*L

A0 to A7 : column address
A9 to A21 : page address
(A13 to A21: block address
A9 to A12 : NAND address in block)

*: A8 is automatically set to "Low" or "High" by the "00H" command or a "01H" command in device inside.
*: I/O 6 to 8 must be set low in the third cycle.

Operation Mode: Logic and Command Tables

The operation modes such as Program, Erase, Read and Reset are controlled by the eleven different command operations shown in Table 3. Address input, command input and data input/output are controlled by the CLE, ALE, $\overline{CE}$, $\overline{WE}$, $\overline{RE}$ and $\overline{WP}$ signals, as shown in Table 2.

Table 2. Logic Table

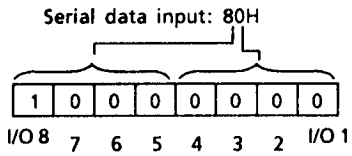
	CLE	ALE	$\overline{CE}$	$\overline{WE}$	$\overline{RE}$	$\overline{WP}$
Command Input	H	L	L	⌐└↗	H	*
Data Input	L	L	L	⌐└↗	H	*
Address Input	L	H	L	⌐└↗	H	*
Serial Data Output	L	L	L	H	↘⌐	*
During Programming (Busy)	*	*	*	*	*	H
During Erasing (Busy)	*	*	*	*	*	H
Program, Erase Inhibit	*	*	*	*	*	L

H: V_{IH}, L: V_{IL}, *: V_{IH} or V_{IL}

Table 3. Command table (HEX data)

	FIRST CYCLE	SECOND CYCLE	ACCEPTABLE COMMAND WHILE BUSY
Serial Data Input	80	-	
Read Mode (1)	00	-	
Read Mode (2)	01	-	
Read Mode (3)	50	-	
Reset	FF	-	○
Auto Program	10	-	
Auto Block Erase	60	D0	
Status Read	70	-	○
ID Read	90	-	

Bit assignment of HEX data
(Example)



Once the device is set to Read mode by the "00H", "01H" or "50H" command, additional Read commands are not needed for sequential page Read operations. Table 4 shows the operation states for Read mode.

Table 4. Read mode operation states

	CLE	ALE	$\overline{CE}$	$\overline{WE}$	$\overline{RE}$	I/O 1 TO I/O 8	POWER
Output Select	L	L	L	H	L	Data output	Active
Output Deselect	L	L	L	H	H	High impedance	Active
Standby	L	L	H	H	*	High impedance	Standby

H : V_{IH} L : V_{IL} * : V_{IH} or V_{IL}

DEVICE OPERATION

Read Mode (1)

Read mode (1) is set by issuing a '00H' command to the command register. Refer to Figure 3 below for timing details and block diagram.

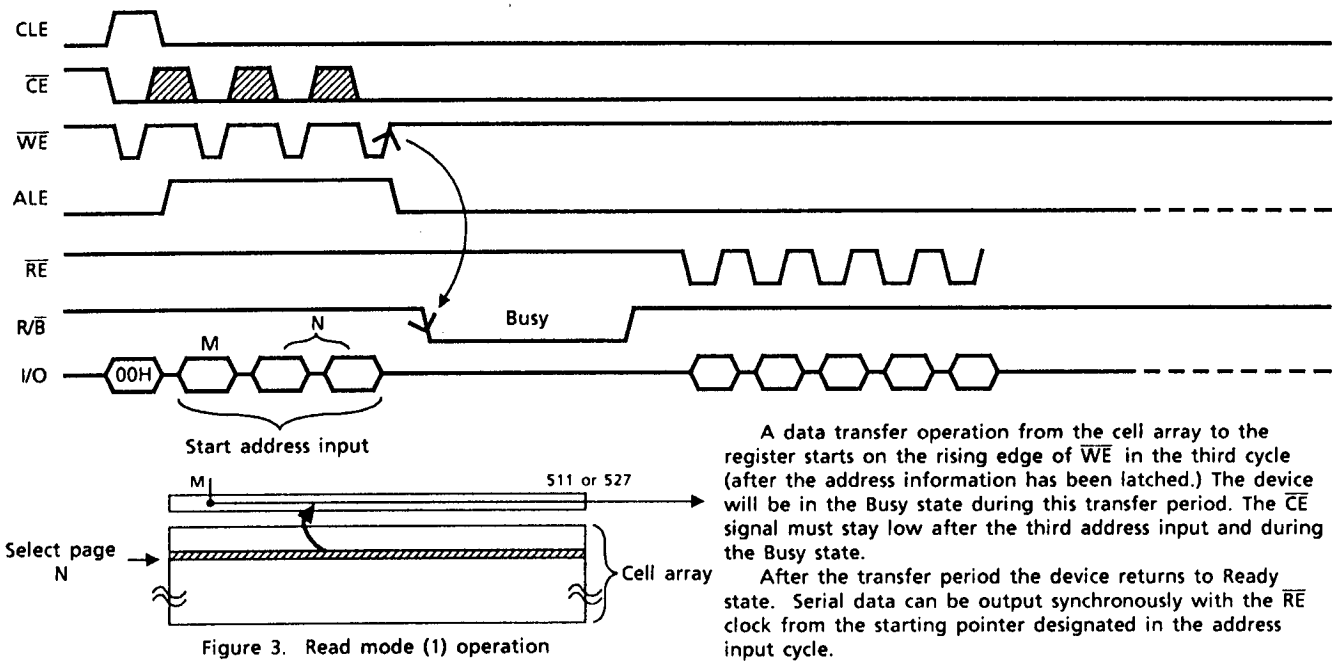


Figure 3. Read mode (1) operation

A data transfer operation from the cell array to the register starts on the rising edge of $\overline{WE}$ in the third cycle (after the address information has been latched.) The device will be in the Busy state during this transfer period. The $\overline{CE}$ signal must stay low after the third address input and during the Busy state.

After the transfer period the device returns to Ready state. Serial data can be output synchronously with the $\overline{RE}$ clock from the starting pointer designated in the address input cycle.

Read Mode (2)

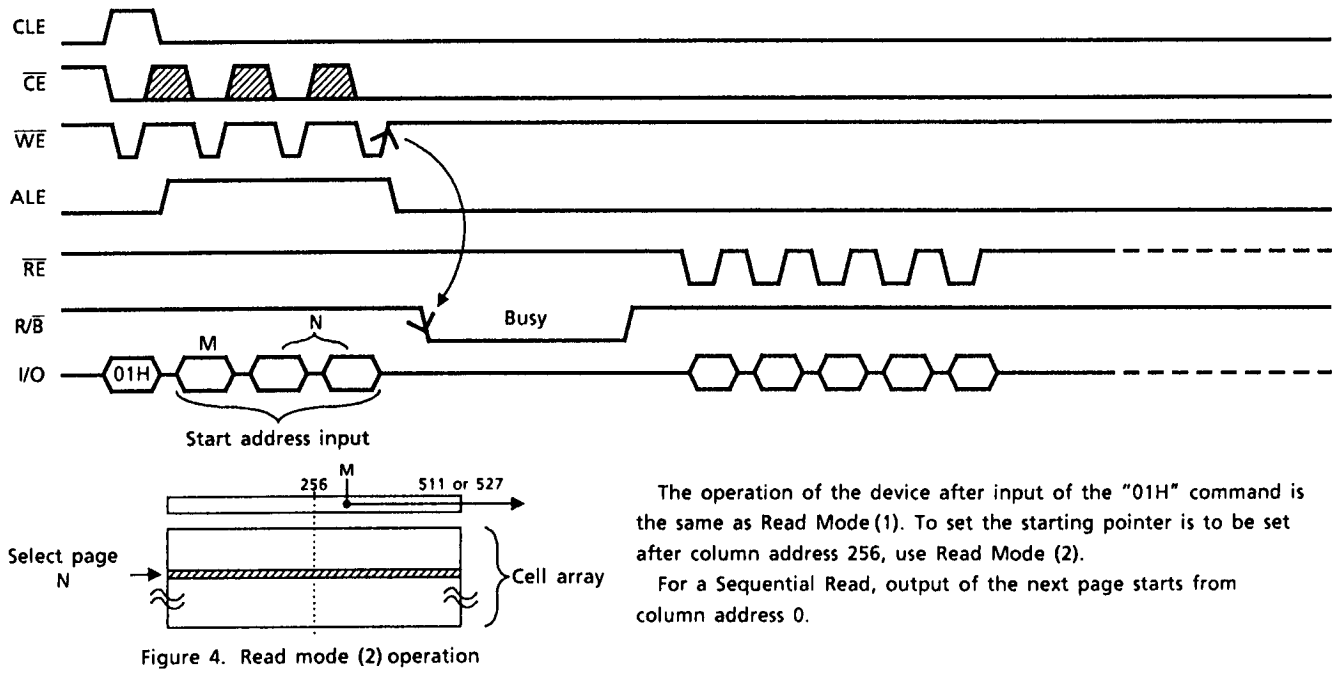


Figure 4. Read mode (2) operation

The operation of the device after input of the "01H" command is the same as Read Mode (1). To set the starting pointer is to be set after column address 256, use Read Mode (2).

For a Sequential Read, output of the next page starts from column address 0.

Read Mode (3)

Read mode (3) has the same timing as Read modes (1) and (2) but is used to access information in the extra 16-byte redundancy area of the page. The starting pointer is therefore assigned between bytes 512 and 527.

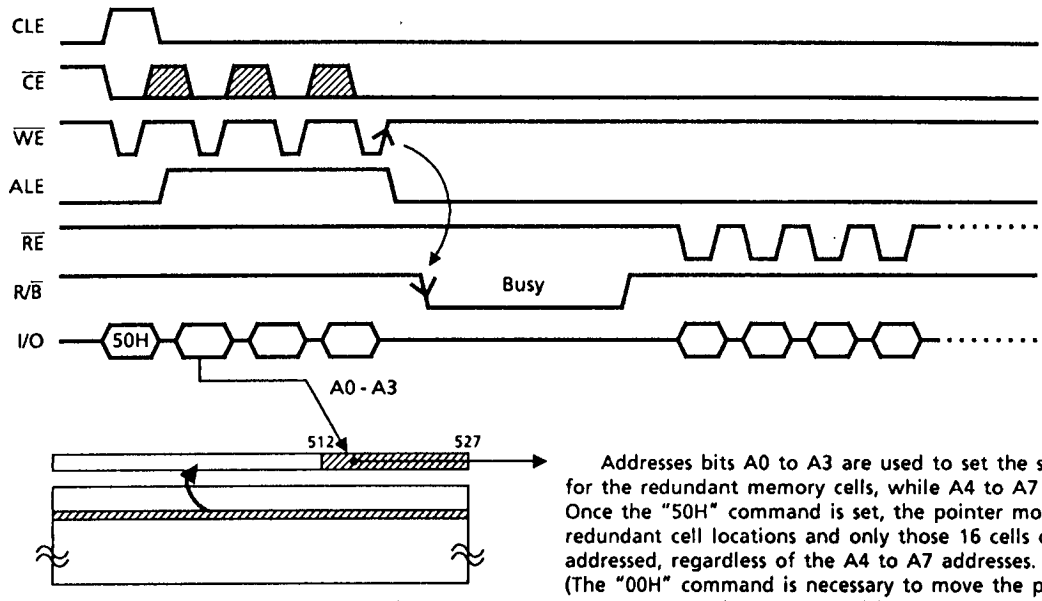
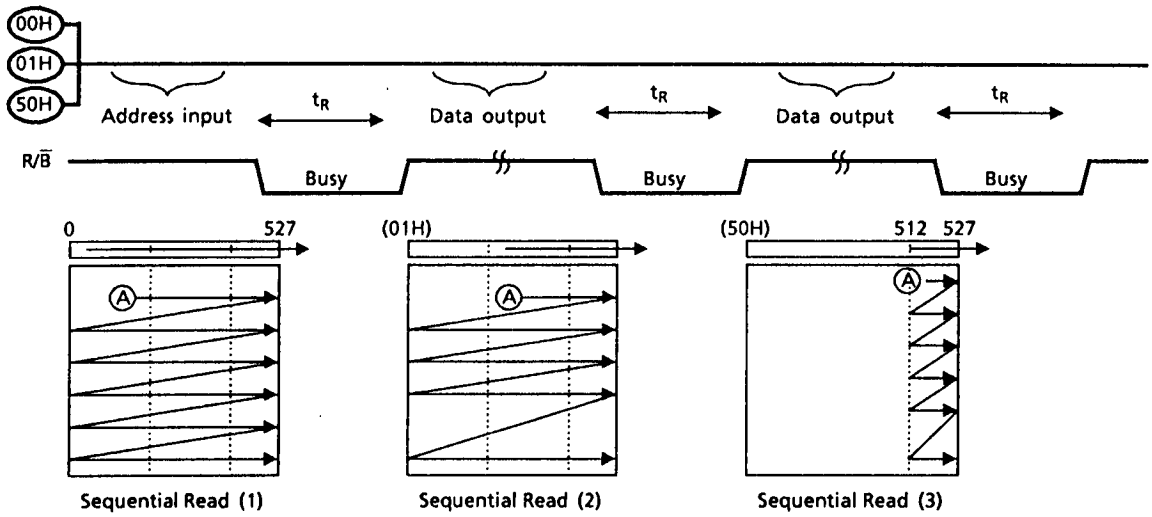


Figure 5. Read mode (3) operation

Addresses bits A0 to A3 are used to set the starting pointer for the redundant memory cells, while A4 to A7 are ignored. Once the "50H" command is set, the pointer moves to the redundant cell locations and only those 16 cells can be addressed, regardless of the A4 to A7 addresses.
(The "00H" command is necessary to move the pointer back to the 0 to 511 main memory cell locations.)
Read mode (3) operation is invalid when OP is at the V_{CC} level.

Sequential Read (1)(2)(3)

This mode allows the sequential reading of pages without additional address input.



Sequential Read modes (1) and (2) output addresses 0 to 527 as shown above while Sequential Read mode (3) outputs the redundant address locations only. When the pointer reaches the last address, the device continues to output the data from this address ** on each $\overline{RE}$ clock signal.

** OP = GND : column address 527.
V_{CC} : column address 511.

Status Read

The device automatically implements the execution and verification of the Program and Erase operations. The Status Read function is used to monitor the Ready/Busy status of the device, determine the pass /fail result of a Program or Erase operation, and determine if the device is in Suspend or Protect mode. The device status is output through the I/O port using the $\overline{RE}$ clock after a "70H" command input. The resulting information is outlined in Table 5.

Table 5. Status output table

	STATUS	OUTPUT	
I/O1	Pass/Fail	Pass : '0'	Fail : '1'
I/O2	Not used	'0'	
I/O3	Not used	'0'	
I/O4	Not used	'0'	
I/O5	Not used	'0'	
I/O6	Not used	'0'	
I/O7	Ready/Busy	Ready : '1'	Busy : '0'
I/O8	Write protect	Protect :'0'	Not Protect : '1'

The Pass/Fail status on I/O1 is only valid when the device is in the Ready state.

An application example with multiple devices is shown in Figure 6.

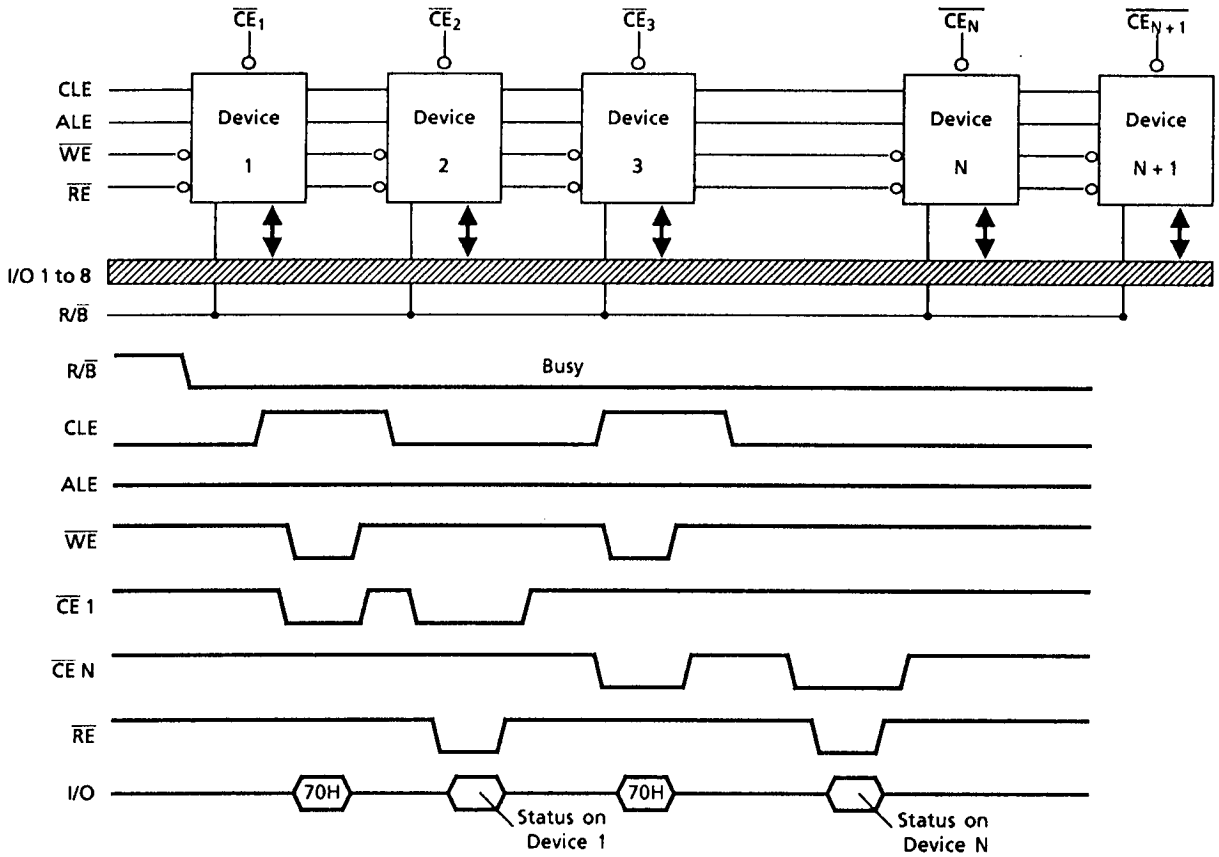
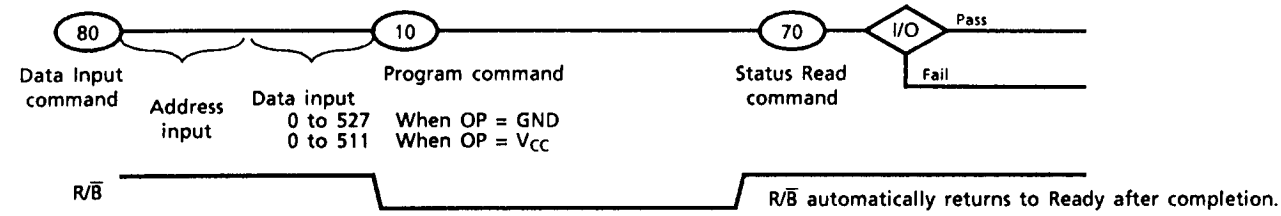


Figure 6. Status read timing application example

SYSTEM DESIGN NOTE : If the R/$\overline{B}$ pin signals of multiple devices are common-wired as shown in the diagram, the Status Read Function can be used to determine the status of each individually selected

Auto Page Program

The device implements the Automatic Page Program operation after receiving a "10H" Program command after the address and data have been input. The sequence of command, address and data input is shown below. (Refer to the detailed timing chart.)



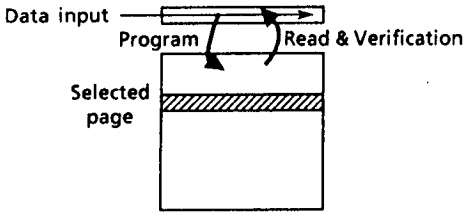
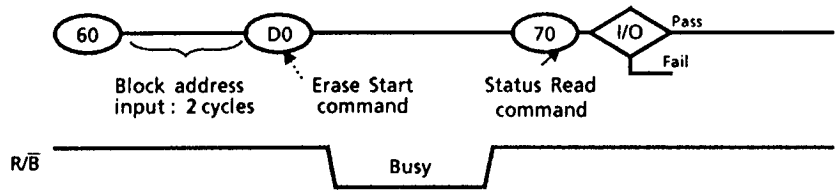


Figure 7. Auto Page Program operation

The data is transferred (programmed) from the register to the selected page on the rising edge of $\overline{WE}$ following the "10H" command input. After programming the programmed data is transferred back to the register to be automatically verified by the device. If the program does not succeed, the above Program/Verify operation is repeated by the device until success is achieved or until the maximum loop number set in the device is reached.

Auto Block Erase

The Auto Block Erase operation starts on the rising edge of $\overline{WE}$ after the Erase Execution command "D0H" which follows the Erase Set-Up command "60H". This two-cycle process for Erase operations acts as an extra layer of protection from accidental erasure of data due to external noise. The device automatically executes the Erase and Verify operations.



Reset

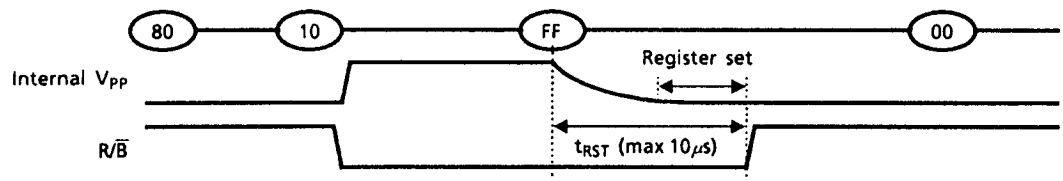
The Reset mode stops all operations. For example, in the case of a Program or Erase operation the regulated voltage is discharged to 0 volts and the device will go into Wait state. The address and data registers are set as follows after a Reset:

- Address Register : All "0"
- Data Register : All "1"
- Operation Mode : Wait State

The response after an "FFH" Reset command is input during each operation is as follows:

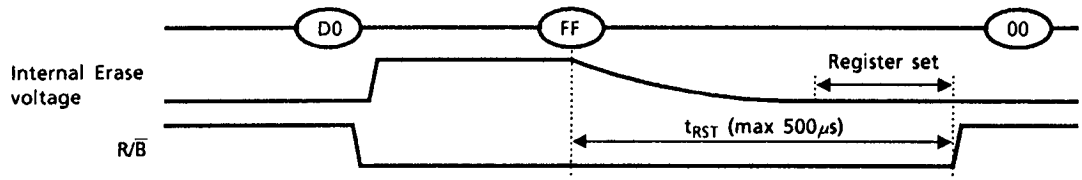
① If the Reset (FFH) command is input during programming :

Figure 8.



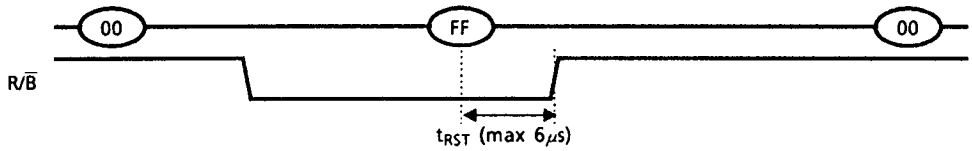
② If the Reset (FFH) command is input during erasing :

Figure 9.



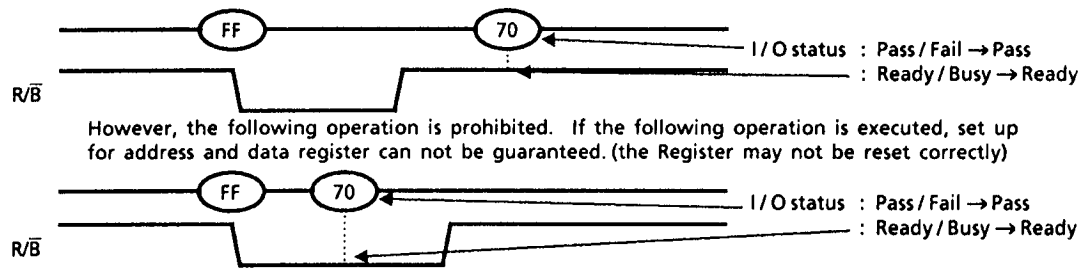
③ If the reset (FFH) command is input during a Read operation :

Figure 10.



⑤ If the Status Read command (70H) is input after a Reset :

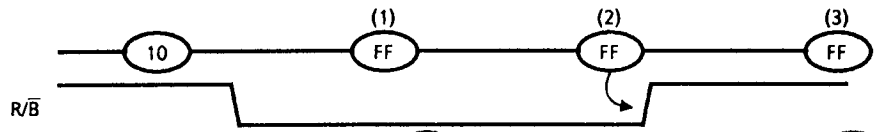
Figure 11.



However, the following operation is prohibited. If the following operation is executed, set up for address and data register can not be guaranteed. (the Register may not be reset correctly)

⑥ If the Reset command is input in succession :

Figure 12.



The second (FF) command is invalid, but the third (FF) command is valid.

ID Read

The TC58V32AFT/ADC contains ID codes to identify the device type and the manufacturer. The ID codes are read out using the following timing conditions:

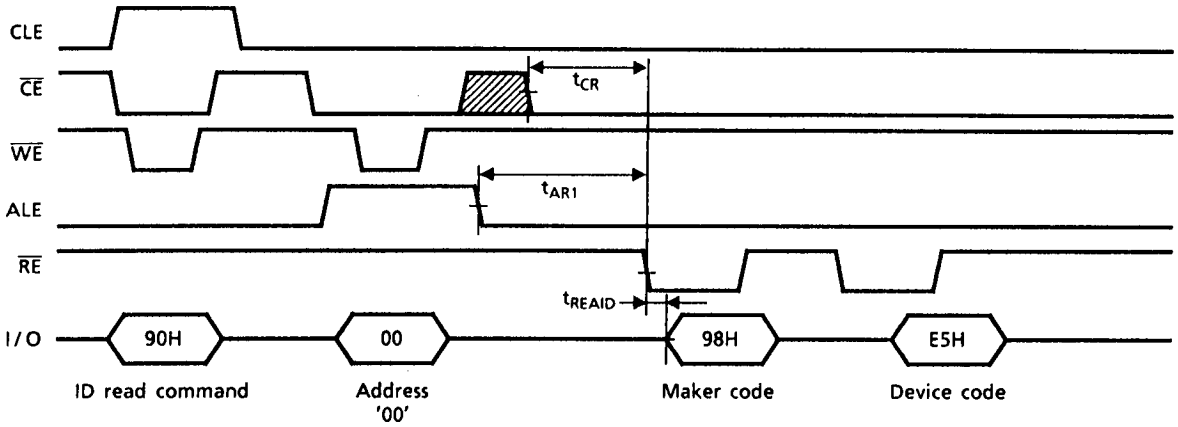


Figure 13. ID read timing

Table 6. Code table

	I/O 8	I/O 7	I/O 6	I/O 5	I/O 4	I/O 3	I/O 2	I/O 1	HEX DATA
Maker code	1	0	0	1	1	0	0	0	98H
Device code	1	1	1	0	0	1	0	1	E5H

For the access time of t_{READ}, t_{CR} and t_{AR1} (refer to the AC Characteristics.)

APPLICATION NOTES AND COMMENTS

(1) Prohibition of unspecified commands

The operation commands are listed in Table 3. Data input as a command other than the specified commands in Table 3 is prohibited. Stored data may be corrupted if an unspecified command is entered during the command cycle.

(2) Pointer control for '00H', '01H', '50H'

The device has three read modes which set the destination of the pointer. Table 7 shows the destination of the pointer, and figure 20 shows the block diagram of their operations.

Table 7. Pointer Destination

READ MODE	COMMAND	POINTER
(1)	00H	0 to 255
(2)	01H	256 to 511
(3)	50H	512 to 527

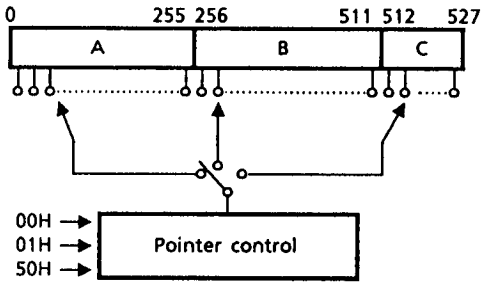
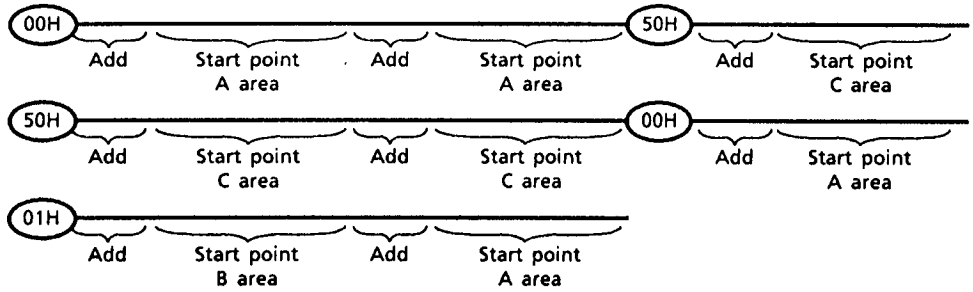


Figure 14. Pointer control

The pointer is set to region 'A' by the '00H' command, to region 'B' by the '01' command, and to region 'C' by the '50H' command.

(Example)

The '00H' command needs to be input to set the pointer back to region 'A' when the pointer points to region 'C'.



For programming into region 'C' only, set the start point to region 'C' with the '50H' command.

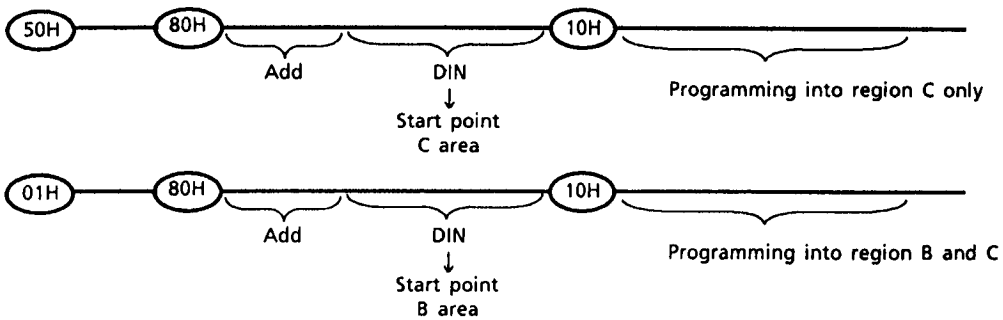


Figure 15. Example of Pointer Setting

(3) Acceptable commands after serial input command '80H'

Once the serial input command ('80H') is input, do not input any command other than the program execution command ('10H') or the reset command ('FFH').

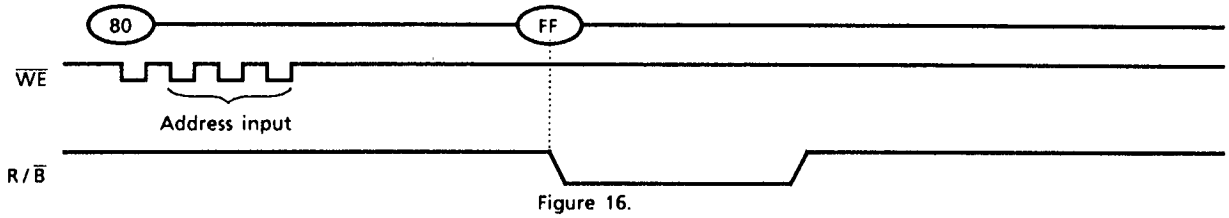
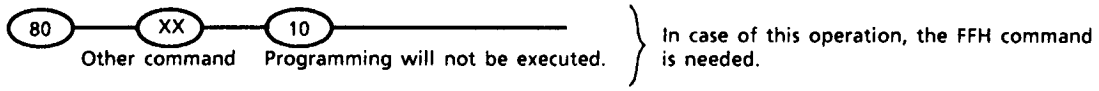


Figure 16.

If a command other than '10H' or 'FFH' is input, the program operation is not performed.



(4) Status read during the read operation

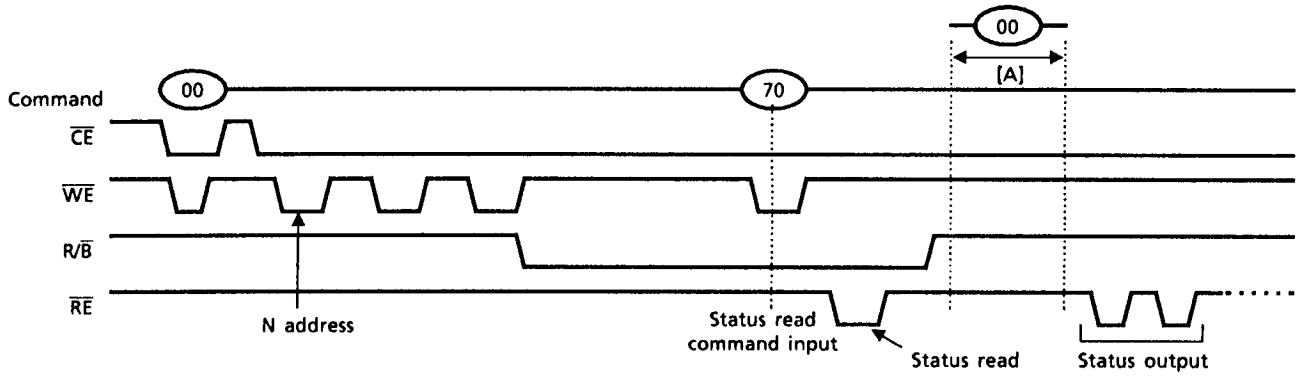


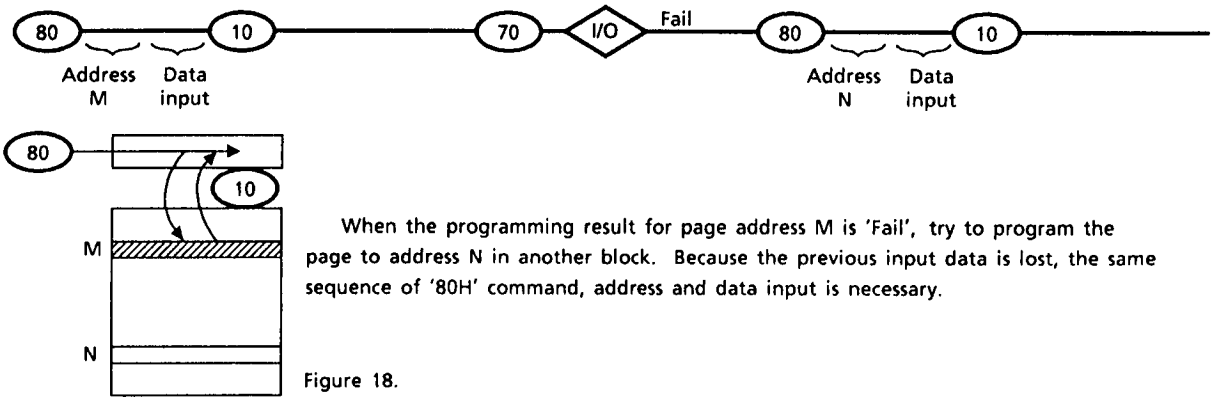
Figure 17.

The device status can be read out by inputting the status read command '70H' during the read mode. Once the device is set to the status read mode after '70H' command input, the device does not return to the read mode.

Therefore, a status read during the read operation is prohibited.

However, when the read command '00H' is input during [A], the status mode is reset, and the device returns to the read mode. In this case, the data output starts from address N without address input.

(5) Auto program failure



When the programming result for page address M is 'Fail', try to program the page to address N in another block. Because the previous input data is lost, the same sequence of '80H' command, address and data input is necessary.

Figure 18.

(6) R/$\overline{B}$: Termination for the Ready / Busy pin (R / $\overline{B}$)

A pull-up resistor needs to be used for termination because the R/$\overline{B}$ buffer consists of an open drain circuit.

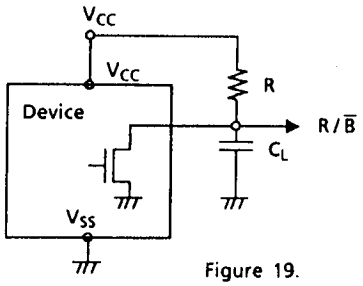
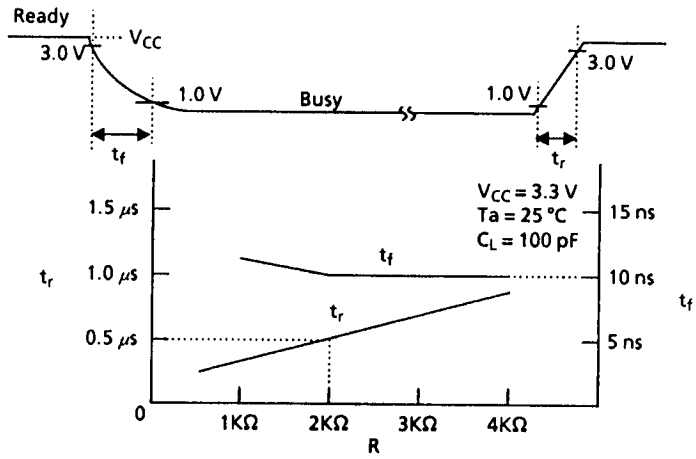


Figure 19.

This data may vary by device.
We recommend that you use this data as a reference when selecting a resistor value.



(7) Status after Power On

Although the device is set to the read mode after power - up, the following sequence is needed because each input signal may not be stable at power on.

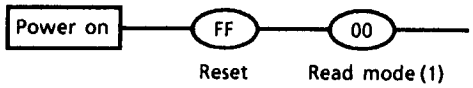


Figure 20.

(8) Power On / Off Sequence :

The $\overline{WP}$ signal is useful for protecting against data corruption at power on / off. The following timing is necessary :

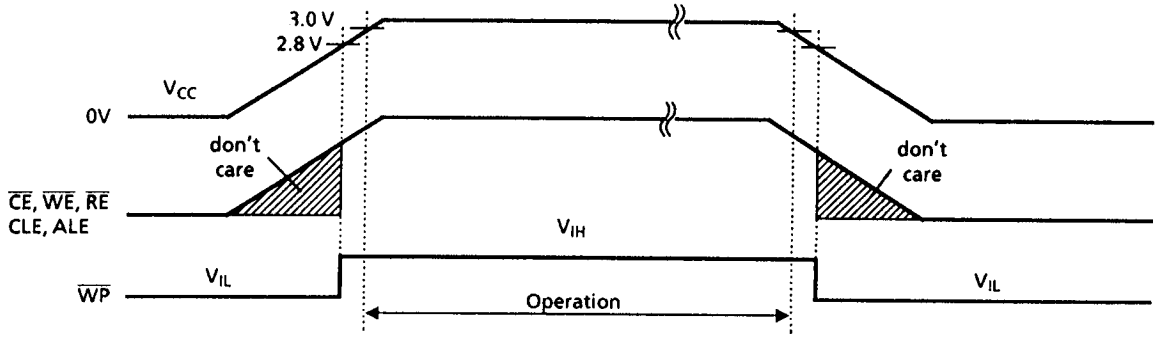
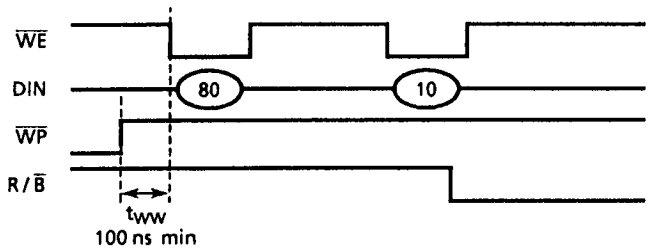


Figure 21. Power On / Off Sequence

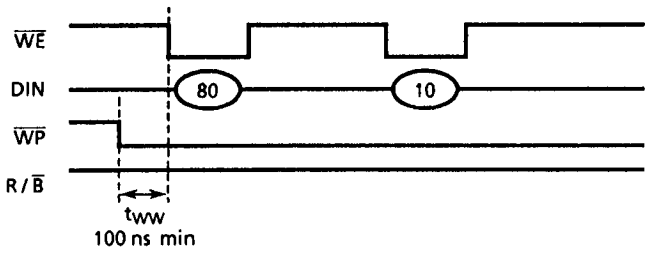
(9) Setup for $\overline{WP}$ Signal

The erase and program operations are compulsively reset when $\overline{WP}$ goes low. The following conditions must be met:

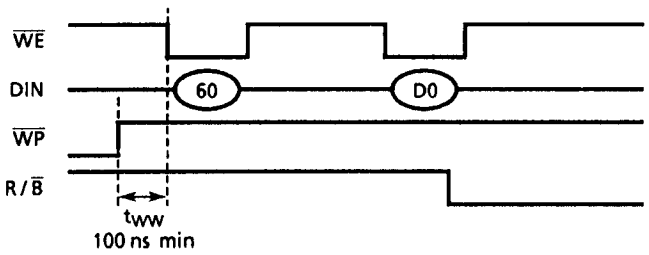
Program



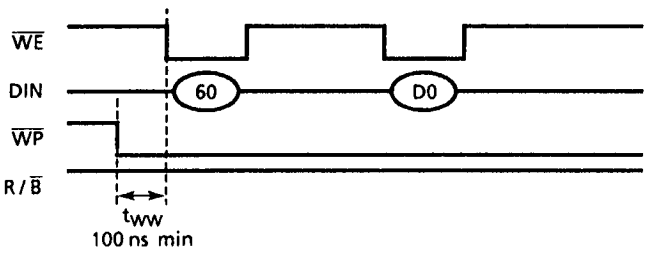
Program Prohibition



Erase



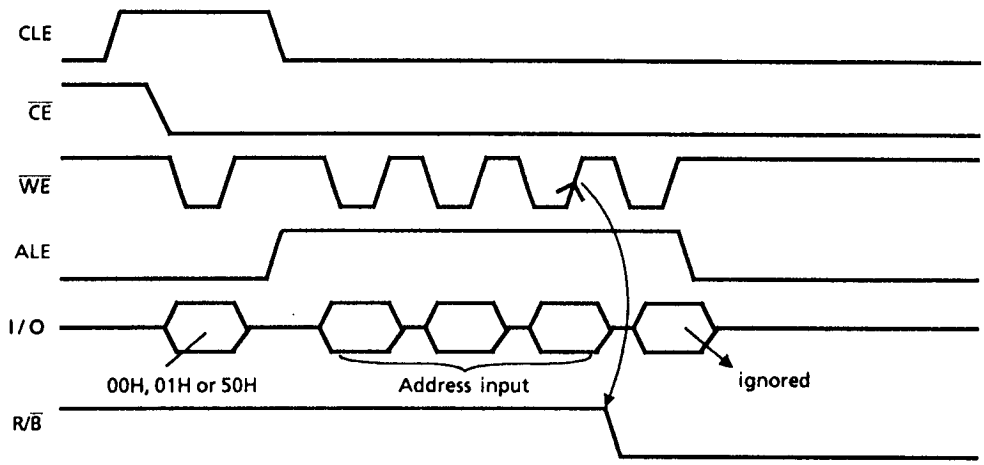
Erase Prohibition



(10) In the case that 4 address cycles are input

Although the device may acquire the fourth address, it is ignored inside the chip.

Read operation



Internal read operation starts when $\overline{WE}$ in the third cycle goes high.

Figure 22.

Program operation

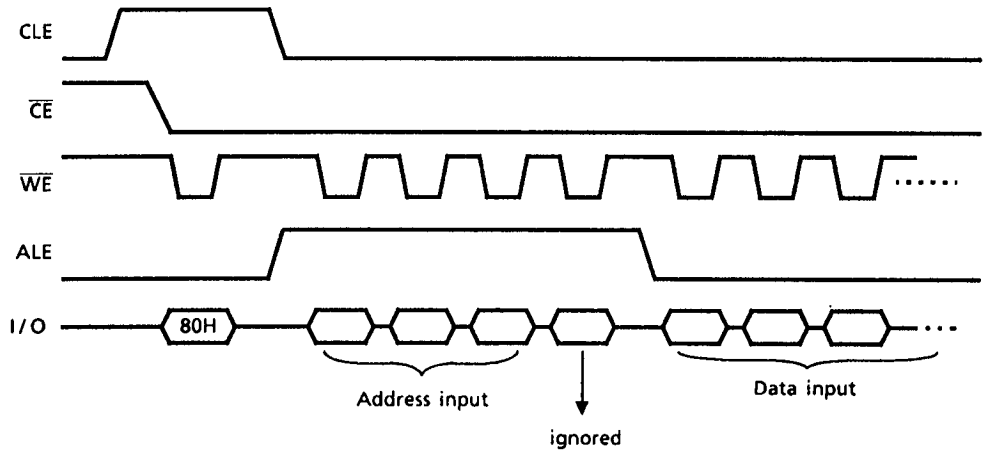


Figure 23.

(11) Divided program in the same page (Partial page program)

The device allows a page to be divided into 10 segments (maximum) with each page segment programmed individually as follows:

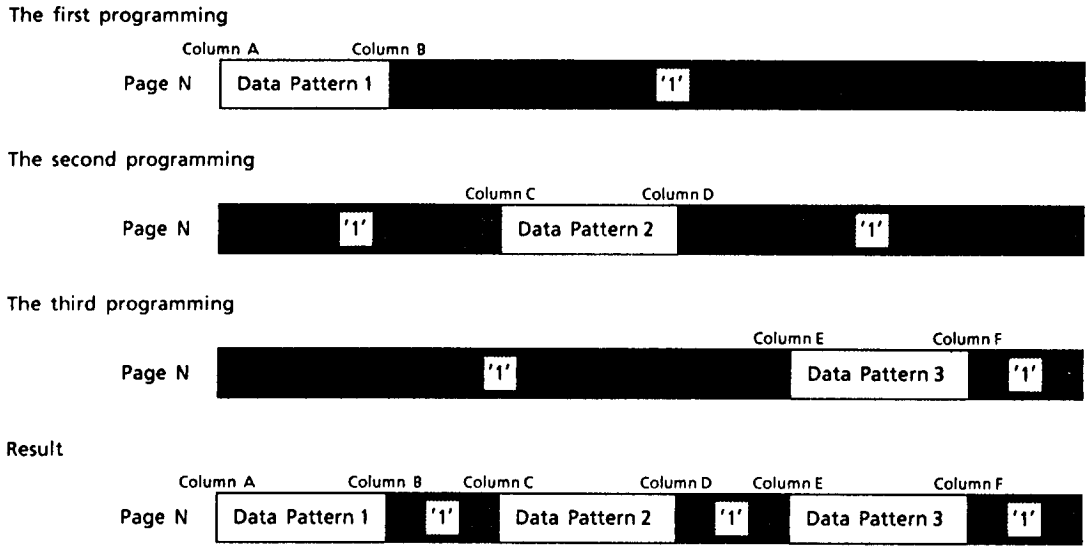


Figure 24.

Note: The input data for unprogrammed or previously programmed page segments must be '1'. (i.e. Mask all page bytes outside the segment to be programmed with '1' data.)

(12) Notification for $\overline{RE}$ Signal

The internal column address counter is incremented synchronously with the $\overline{RE}$ clock in the read mode. Therefore, once the device is set into the read mode by the '00H', '01H' or '50H' command, the internal column address counter is incremented by the $\overline{RE}$ clock independent of (before or after) the address input. Assuming that the $\overline{RE}$ clocks are inputted before address input and the pointer reaches the last column address, internal read operation (array → register) will occur and the device will be in the busy state. (Refer to Figure 25)

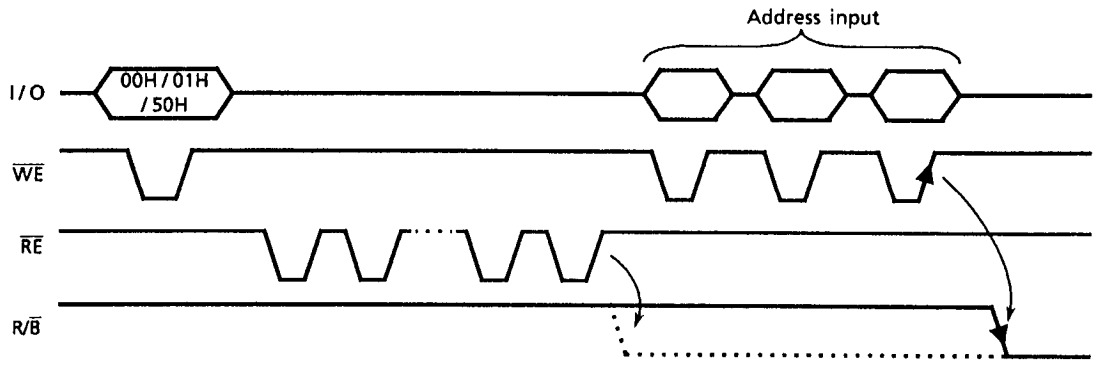


Figure 25.

Therefore, $\overline{RE}$ clocks must occur after the address input.

(13) Invalid block (bad block)

The device contains unusable blocks. Therefore, the following issues must be recongnized:

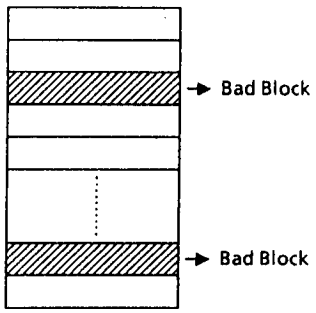


Figure. 26

Check if the device has any bad blocks after device installation into the system. Do not try to access bad blocks. A bad block does not affect the performance of good blocks becasue it is isolated from the bit line by the select gate.

The number of valid blocks is as follows:

	MIN	TYP	MAX	UNIT
Valid (Good) Block Number	502	508	512	Block

Figure 28 shows the bad block test flow.

(14) Failure Phenomena for Program and Erase Operations.

The device may fail during program or erase operation.

The following possible failure modes should be considered when inplementing a highly reliable system.

FAILURE MODE		DETECTION AND COUNTERMEASURE SEQUENCE
Block	Erase Failure	Status Read after Erase → Block Replacement
Page	Program Failure	Status Read after Prog. → Block Replacement
Single Bit*	Program Failure '1' → '0'	(1) Block Verify after Prog. → Retry
		(2) ECC

* : (1) or (2)

- ECC : Error Correcting code → Hamming Code etc.
  Example : 1 bit correction & 2 bit detection.
- Block Replacement

Program

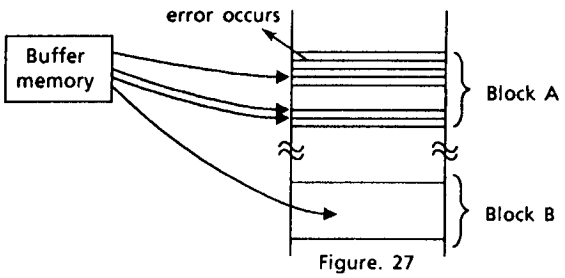


Figure. 27

When an error happens in Block A, try to reprogram the data into another (Block B) by loading from an external buffer. Then, prevent further system accesses to Block A (by creating a 'bad block' table or an another appropriate scheme.)

Erase

When an error occurs for an erase operation, prevent future accesses to this bad block (again by creating a table within the system or other appropriate scheme).

BAD BLOCK TEST FLOW

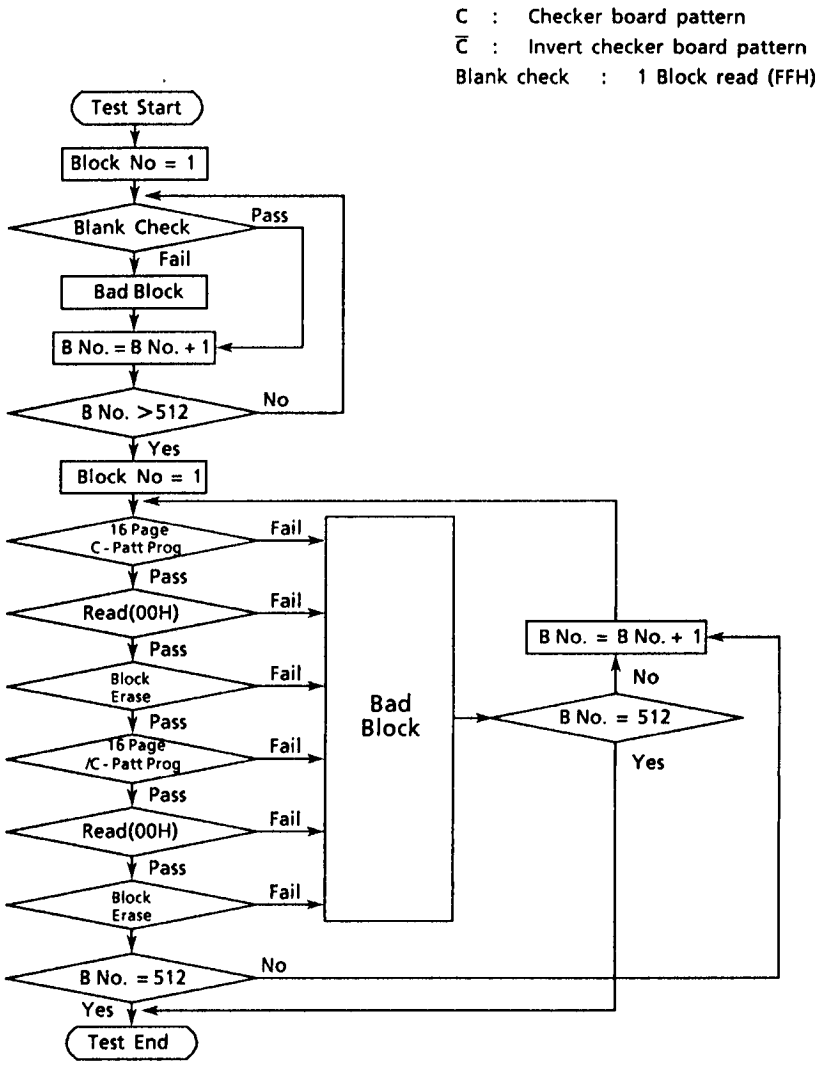


Figure 28.

ATTENTION

(1) Avoid bending or subjecting the card to sudden impact.

(2) Avoid touching the connectors so as to avoid damage from static electricity.
This card should be kept in the antistatic film case when not in use.

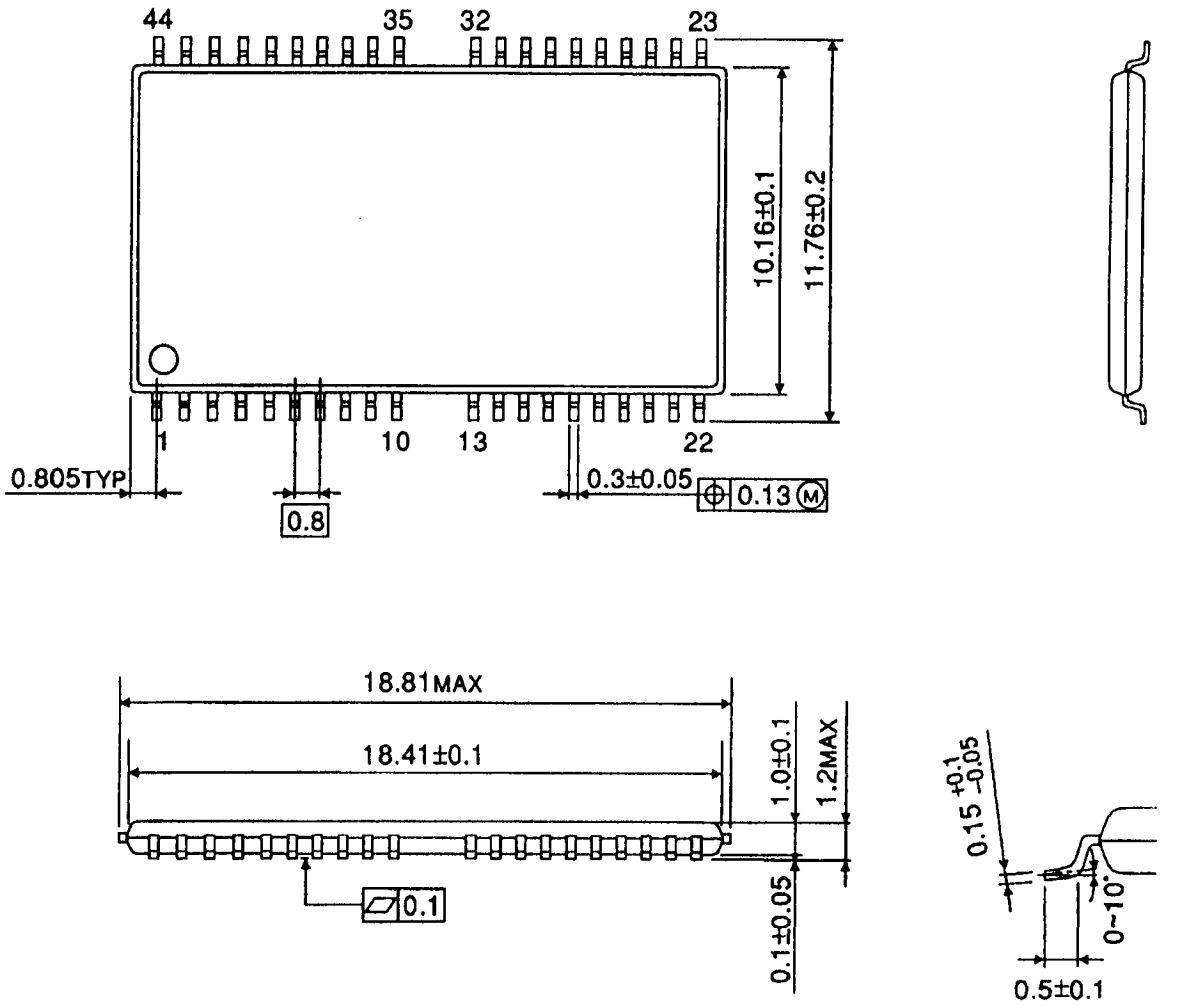
(3) Toshiba cannot accept, and hereby disclaims liability for, any damage to the card including data corruption that may occur because of mishandling.

PACKAGE DIMENSIONs

Plastic TSOP

TSOP II 44/40 - P - 400 - 0.80B

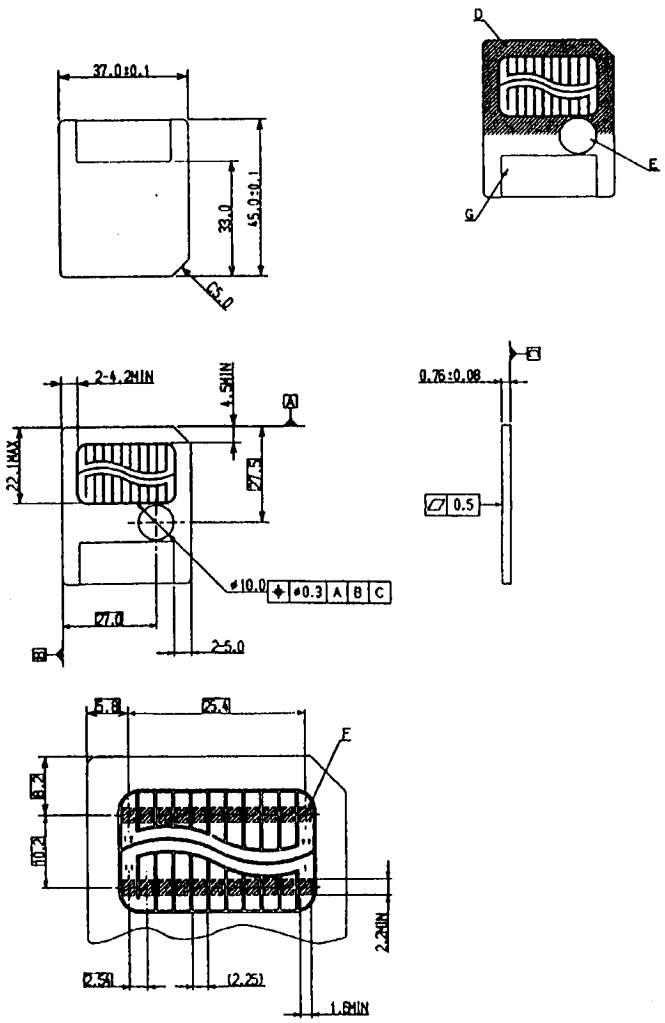
UNITS : mm



PACKAGE DIMENSIONS

FDC-22A

UNITS: mm



Contact area (2 : 1)

E : Write protect area

F : The distance between the surface of D and all contact areas is less than 0.1 mm.

G: Index area